

# **EE 240C**

## **Analog-Digital Interface Integrated Circuits**

### **Dynamic Errors**

# Dynamic Performance Metrics

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- Time domain
  - Glitch impulse, aperture uncertainty, settling time, ...
  - We'll look at these later, in the context of specific circuits
- Frequency domain
  - Performance metrics follow from looking at converter or building block output spectrum
    - "Spectral performance metrics"
  - Basic idea: Apply one or more tones at converter input
    - Expect same tone(s) at output, all other frequency components represent nonidealities
  - Important to realize that both static (DNL, INL) and dynamic errors contribute to frequency domain non-ideality

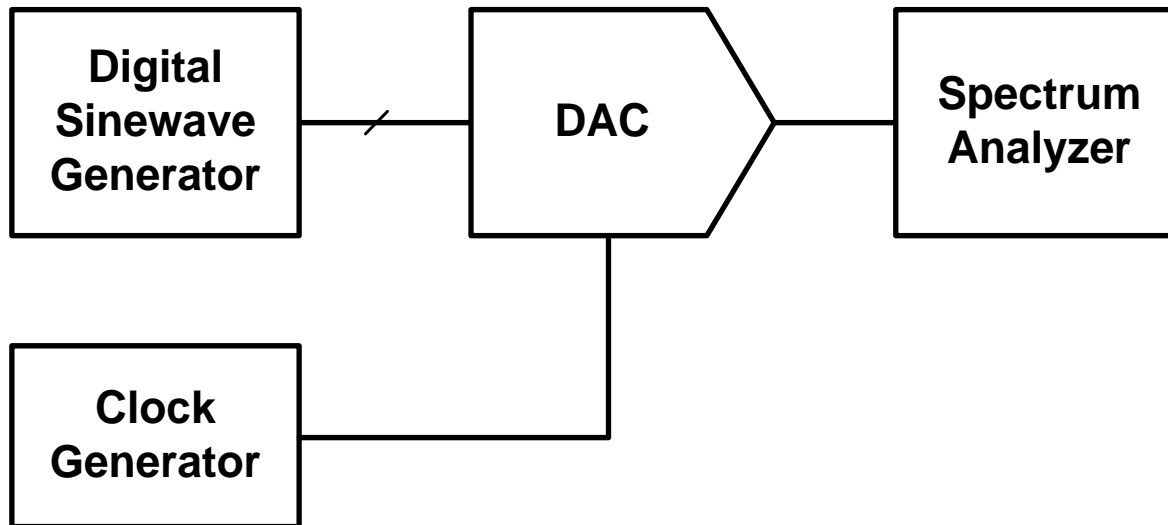
# Alphabet Soup of Spectral Metrics

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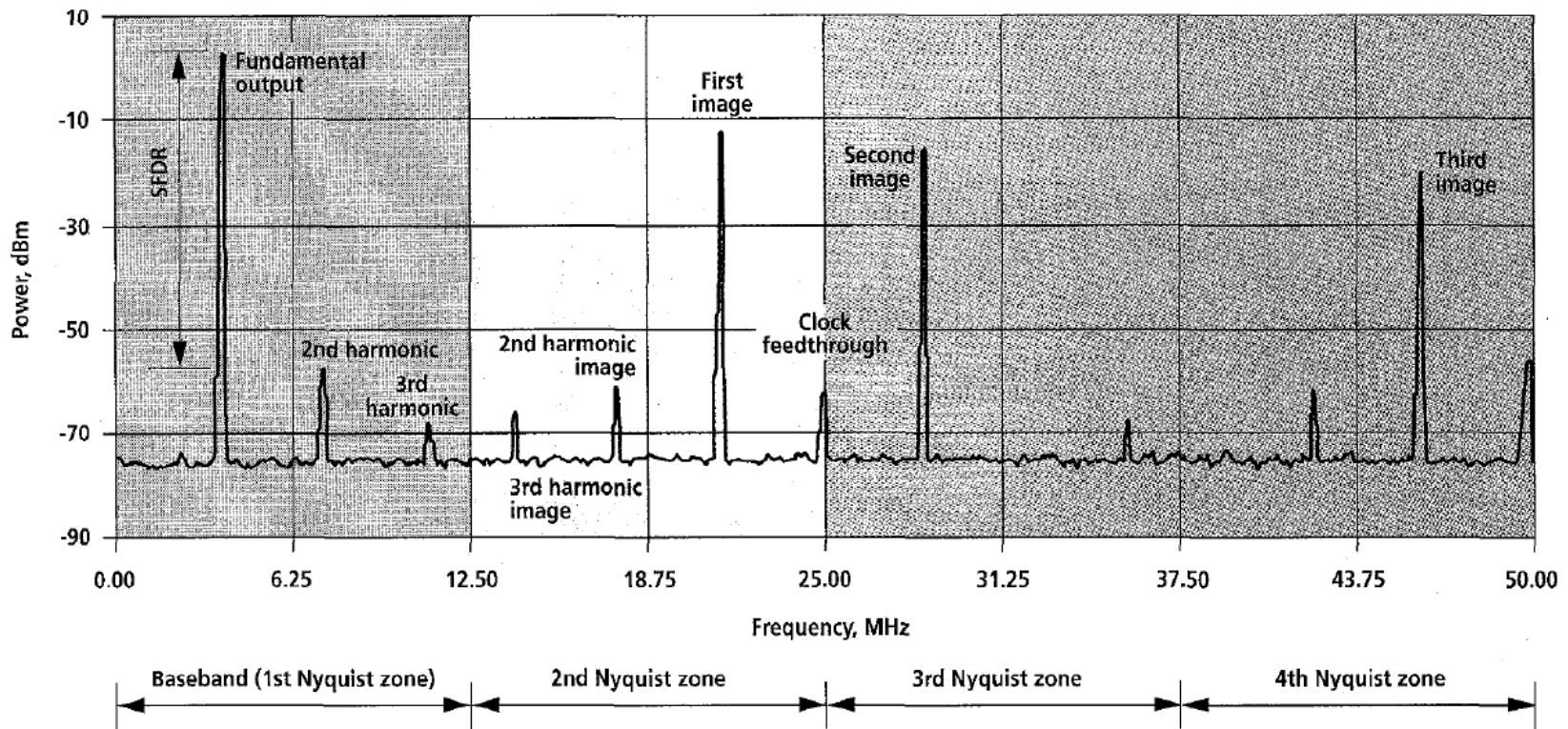
- SNR – Signal-to-noise ratio
- SNDR (SINAD) – Signal-to-(noise+distortion) ratio
- ENOB – Effective number of bits
- DR – Dynamic range
- SFDR – Spurious free dynamic range
- THD – Total harmonic distortion
- ERBW – Effective Resolution Bandwidth
- IMD – Intermodulation distortion
- MTPR – Multi-tone power ratio

# DAC Tone Test/Simulation

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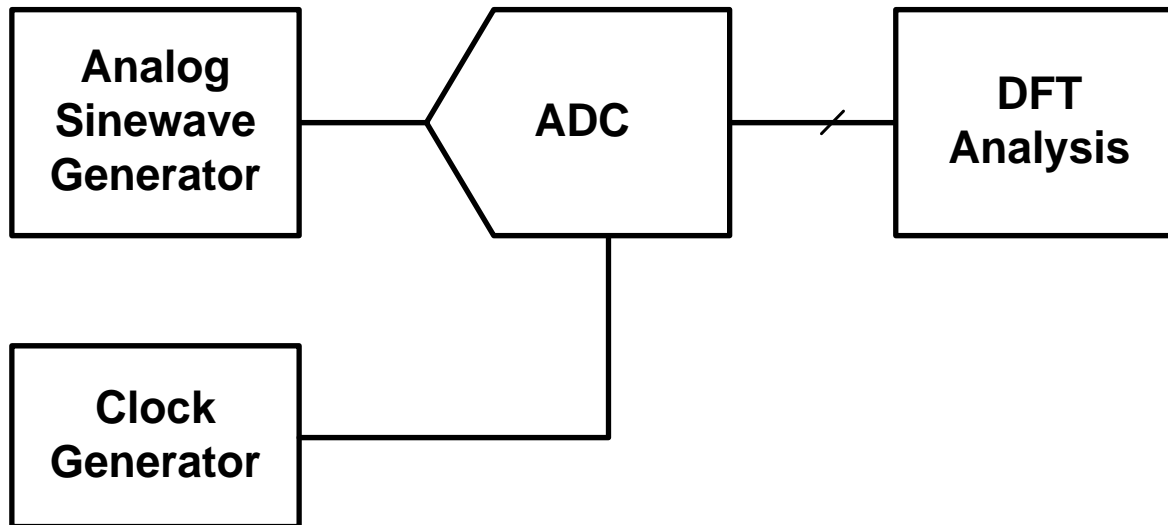
# Typical DAC Output Spectrum



[Hendriks, "Specifying Communications DACs, IEEE Spectrum, July 1997]

# ADC Tone Test/Simulation

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# **EE 240C**

## **Analog-Digital Interface Integrated Circuits**

### **Spectral Analysis**

# Discrete Fourier Transform

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- DFT takes a block of  $N$  time domain samples (spaced  $T_s=1/f_s$ ) and yields a set of  $N$  frequency bins

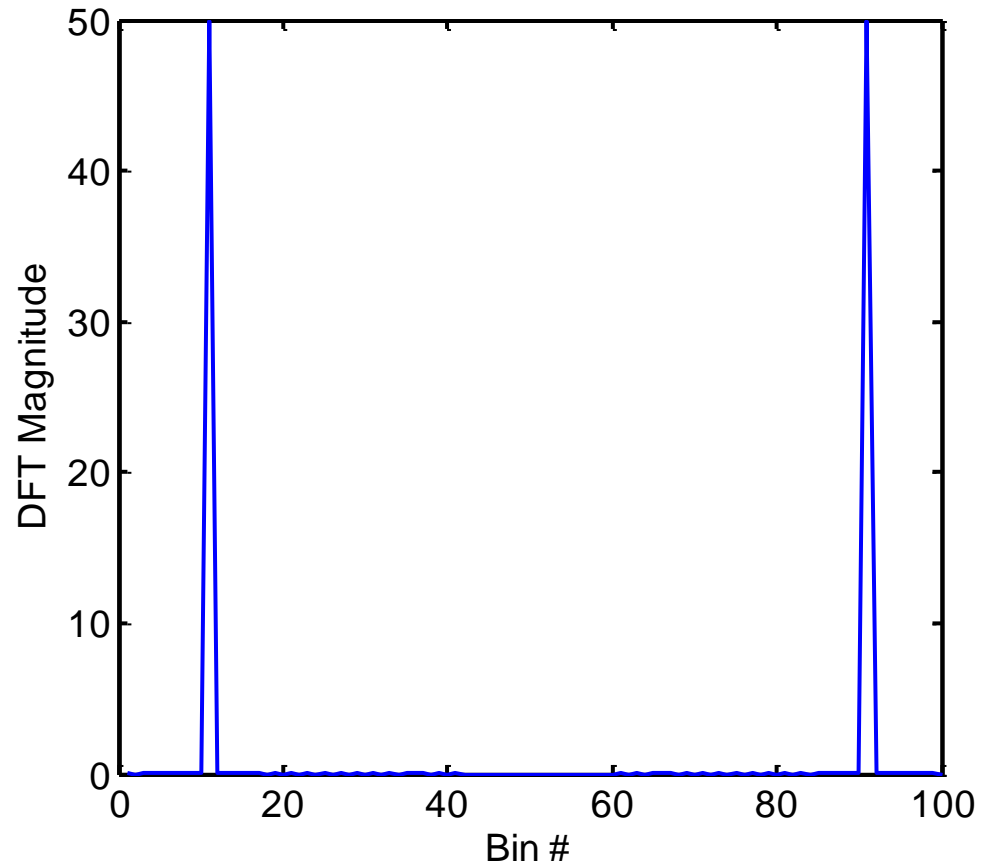
$$X(k) = \sum_{n=0}^{N-1} x(n)e^{-j2\pi kn/N}$$

- Bin  $k$  represents frequency content at  $k \cdot f_s / N$  [Hz]
- DFT frequency resolution
  - Proportional to  $1/(N \cdot T_s)$  in [Hz/bin]
  - $N \cdot T_s$  is total time spent gathering samples
- A DFT with  $N=2^{\text{integer}}$  can be found using a computationally efficient algorithm
  - FFT = Fast Fourier Transform



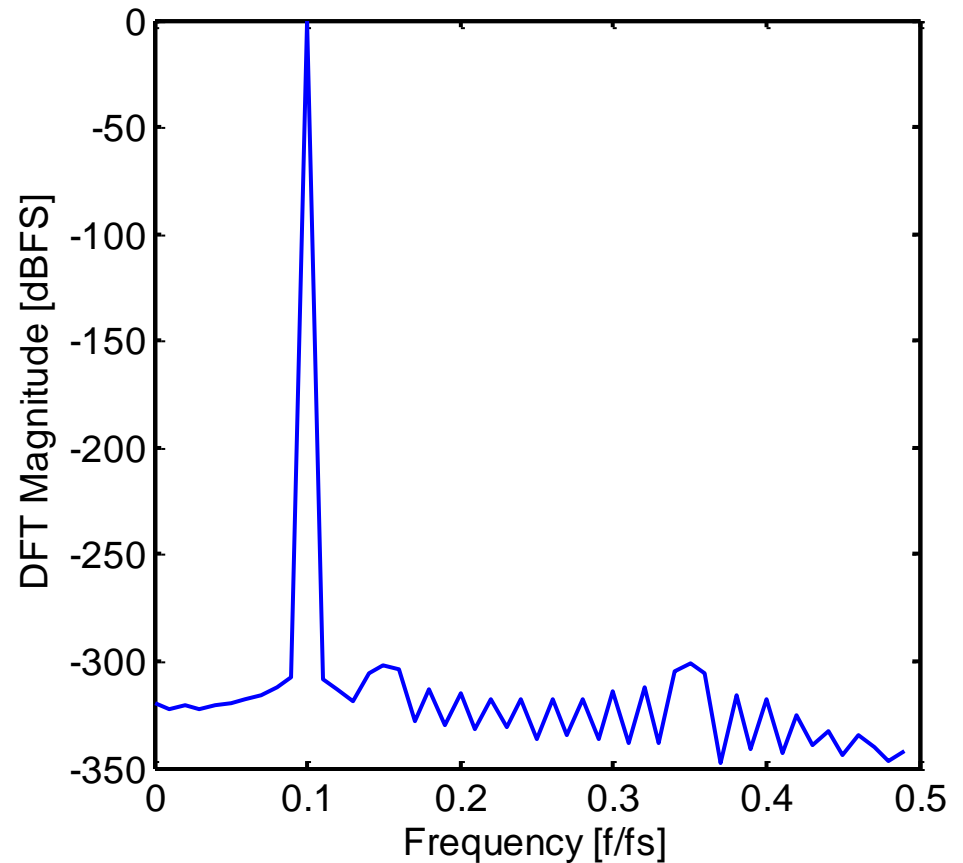
# Matlab Example

```
N = 100;  
fs = 1000;  
fx = 100;  
  
x = cos(2*pi*fx/fs*[0:N-1]);  
s = abs(fft(x));  
plot(s, 'linewidth', 2);
```



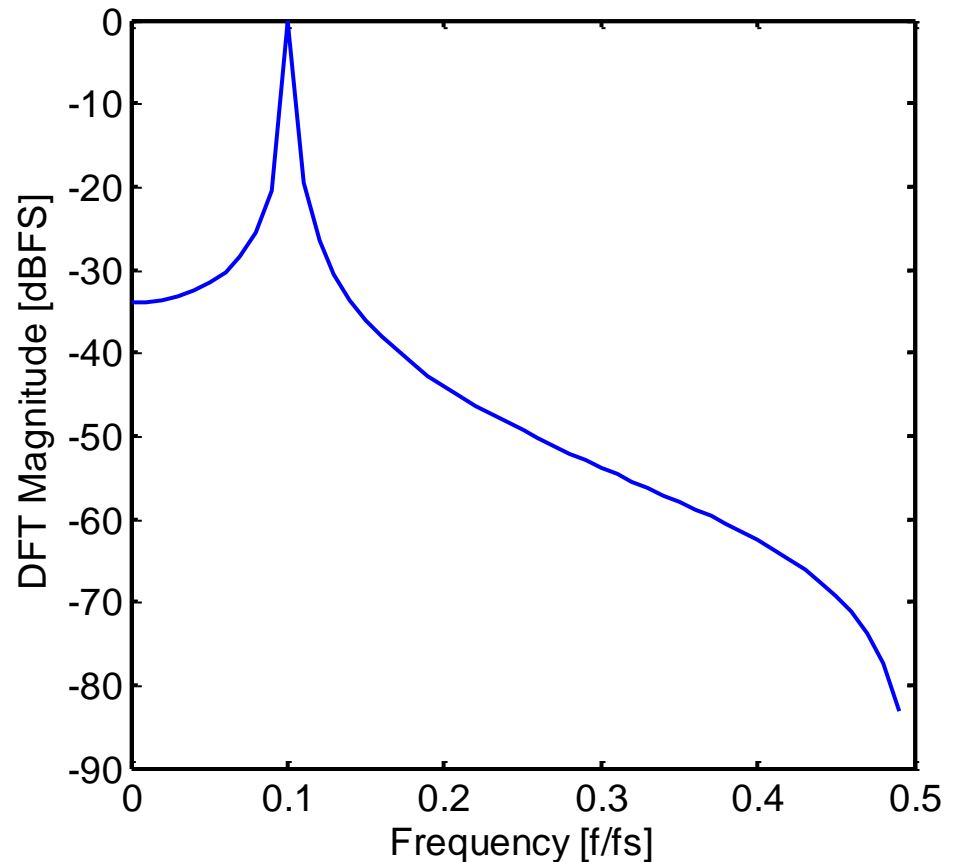
# Normalized Plot with Frequency Axis

```
N = 100;  
fs = 1000;  
fx = 100;  
FS = 1; % full-scale amplitude  
  
x = FS*cos(2*pi*fx/fs*[0:N-1]);  
s = abs(fft(x));  
% remove redundant half of spectrum  
s = s(1:end/2);  
% normalize magnitudes to dBFS  
% dBFS = dB relative to full-scale  
s = 20*log10(2*s/N/FS);  
% frequency vector  
f = [0:N/2-1]/N;  
  
plot(f, s, 'linewidth', 2);  
xlabel('Frequency [f/fs]')  
ylabel('DFT Magnitude [dBFS]')
```



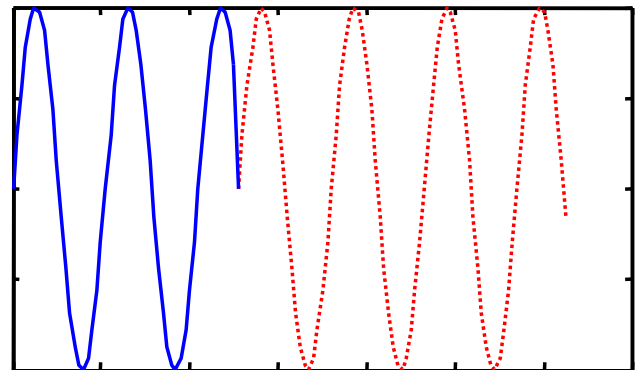
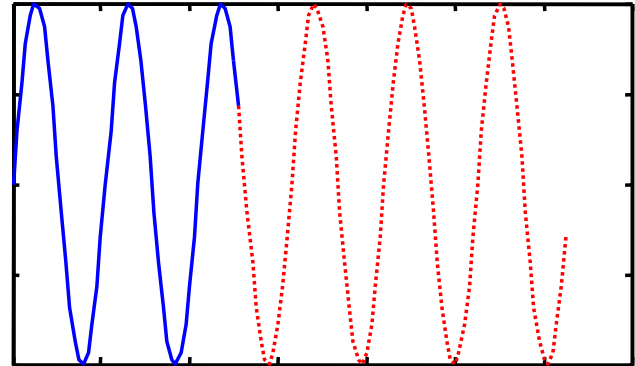
# Another Example

- Same as before, but now  $f_x = 101$
- This doesn't look the spectrum of a sinusoid...
- What's going on?



# Spectral Leakage

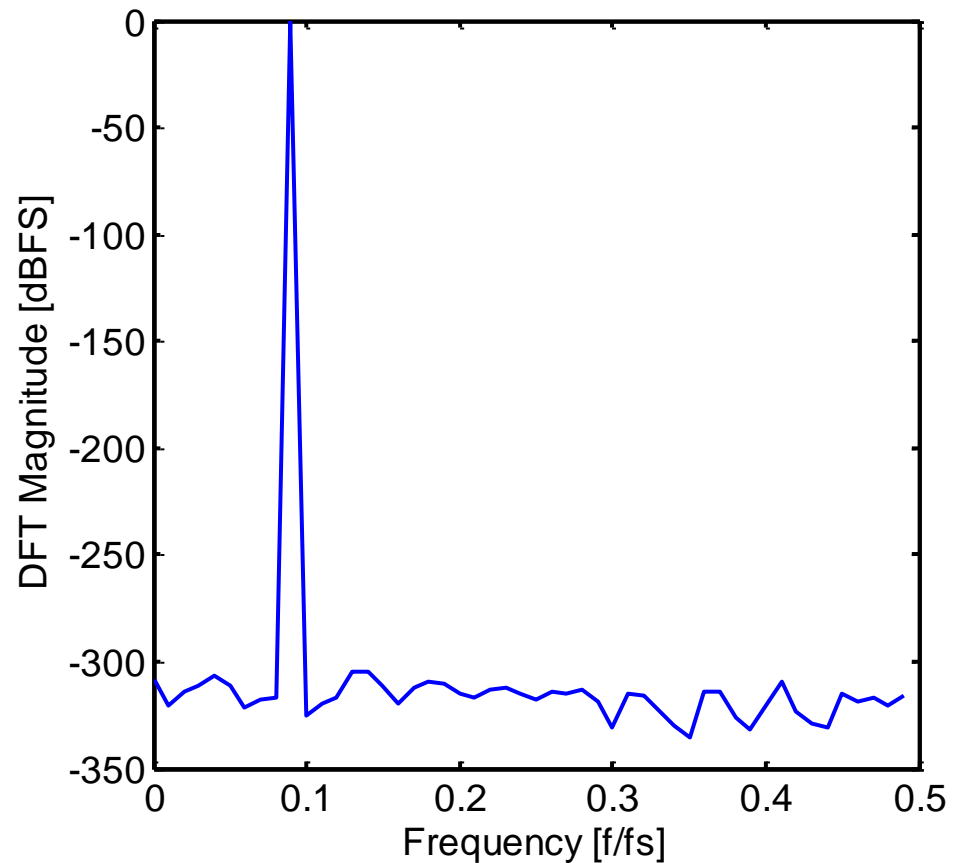
- DFT implicitly assumes that data repeats every  $N$  samples
- A sequence that contains a non-integer number of sine wave cycles has discontinuities in its periodic repetition
  - Discontinuity looks like a high frequency signal component
  - Power spreads across spectrum
- Two ways to deal with this
  - Ensure integer number of periods
  - Windowing



# Integer Number of Cycles

```
N = 100;  
cycles = 9;  
fs = 1000;  
fx = fs*cycles/N;
```

- Usable test frequencies are limited to a multiple of  $f_s/N$



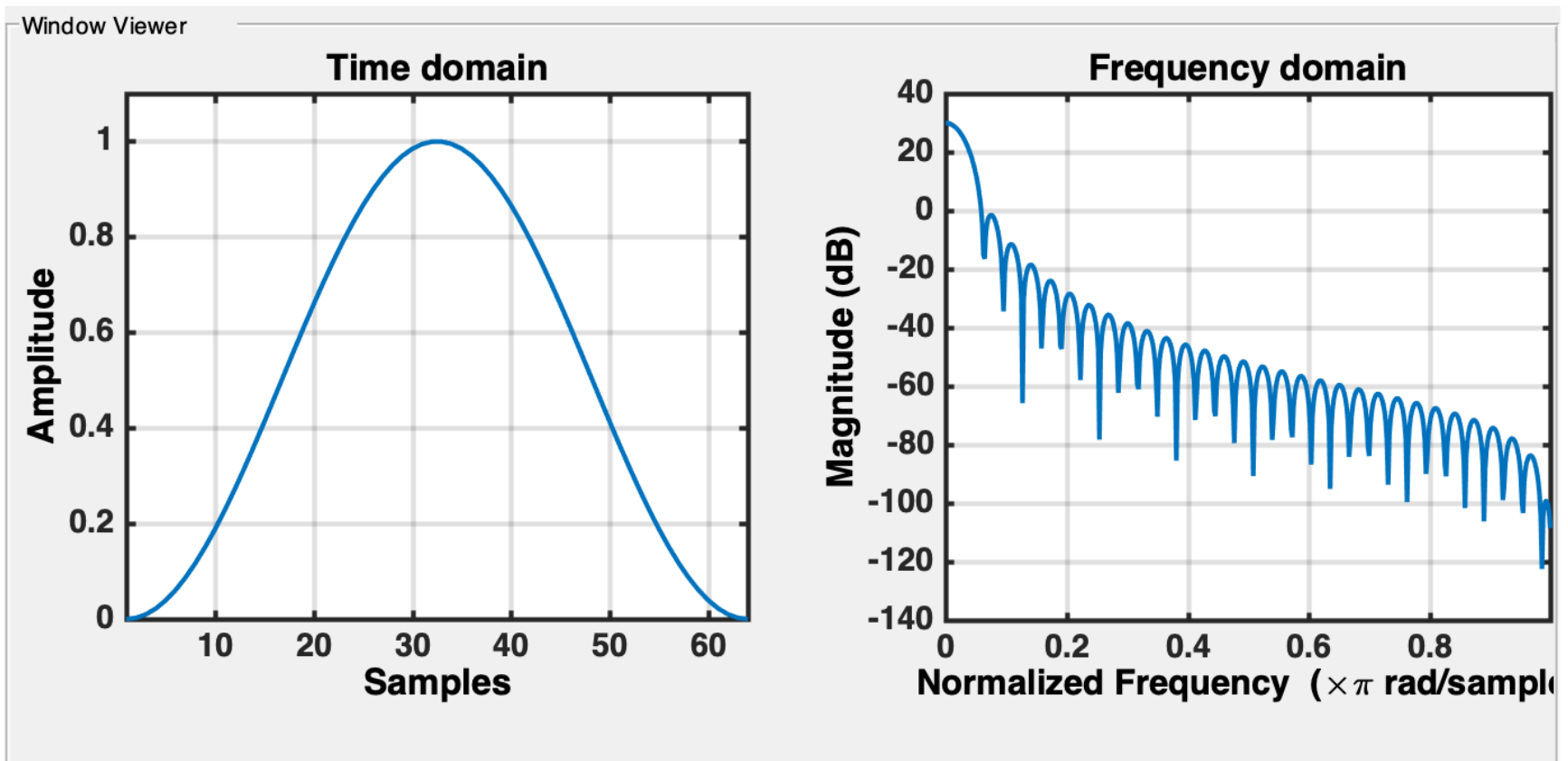
# Windowing

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- Spectral leakage can be attenuated by windowing the time samples prior to the DFT
- Windows taper smoothly down to zero at the beginning and the end of the observation window
- Time domain samples are multiplied by window coefficients on a sample-by-sample basis
  - Means convolution in frequency
  - Sine wave tone and other spectral components smear out over several bins
- Lots of window functions to choose from
  - Tradeoff: attenuation versus smearing
- Example: Hann Window

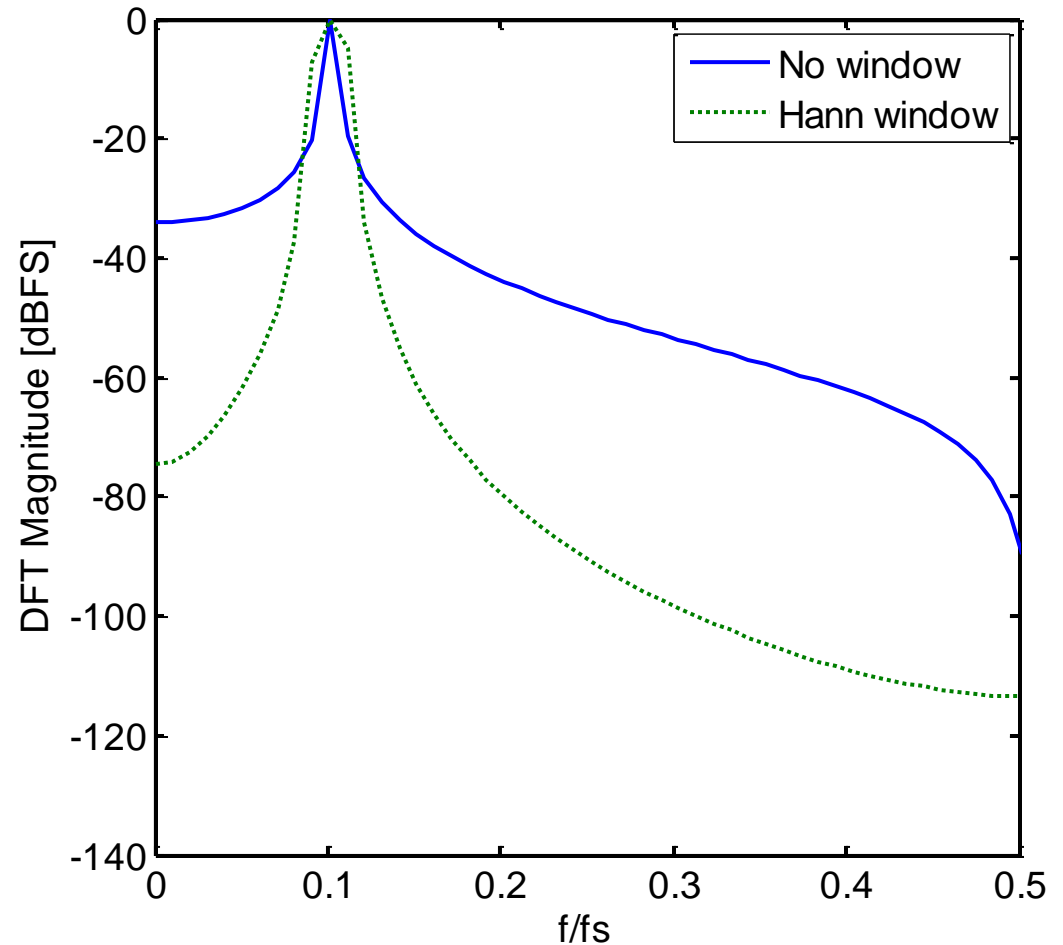
# Hann Window

```
N=64;  
wvtool(hann(N))
```



# Spectrum with Window

```
N = 100;  
fs = 1000;  
fx = 101;  
A = 1;  
  
x = A*cos(2*pi*fx/fs*[0:N-1]);  
s = abs(fft(x));  
x1 = x.*hann(N);  
s1 = abs(fft(x1));
```





# Integer Cycles versus Windowing

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- Integer number of cycles
  - Test signal falls into single DFT bin
  - Requires careful choice of signal frequency
  - Ideal for simulations
  - For lab measurements, lock sampling and signal frequency generators (PLL)
    - "Coherent sampling":  $f_{\text{in}} = \frac{J}{M} f_s$  for M samples and  $\text{GCD}(J, M) = 1$
- Windowing
  - No restrictions on signal frequency
  - Signal and harmonics distributed over several DFT bins
    - Beware of smeared out nonidealities...
  - Requires more samples for given accuracy
- More info
  - [http://www.maxim-ic.com/appnotes.cfm/appnote\\_number/1040](http://www.maxim-ic.com/appnotes.cfm/appnote_number/1040)

# **EE 240C**

## **Analog-Digital Interface Integrated Circuits**

### **Converter Spectral Analysis**

# Quantization Noise Spectrum

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Example:

- Spectral analysis to evaluate (simulated) quantizer performance
- First look at quantization noise introduced by an ideal quantizer

```
N = 2048;
cycles = 67;
fs = 1000;
fx = fs*cycles/N;
LSB = 2/2^10;

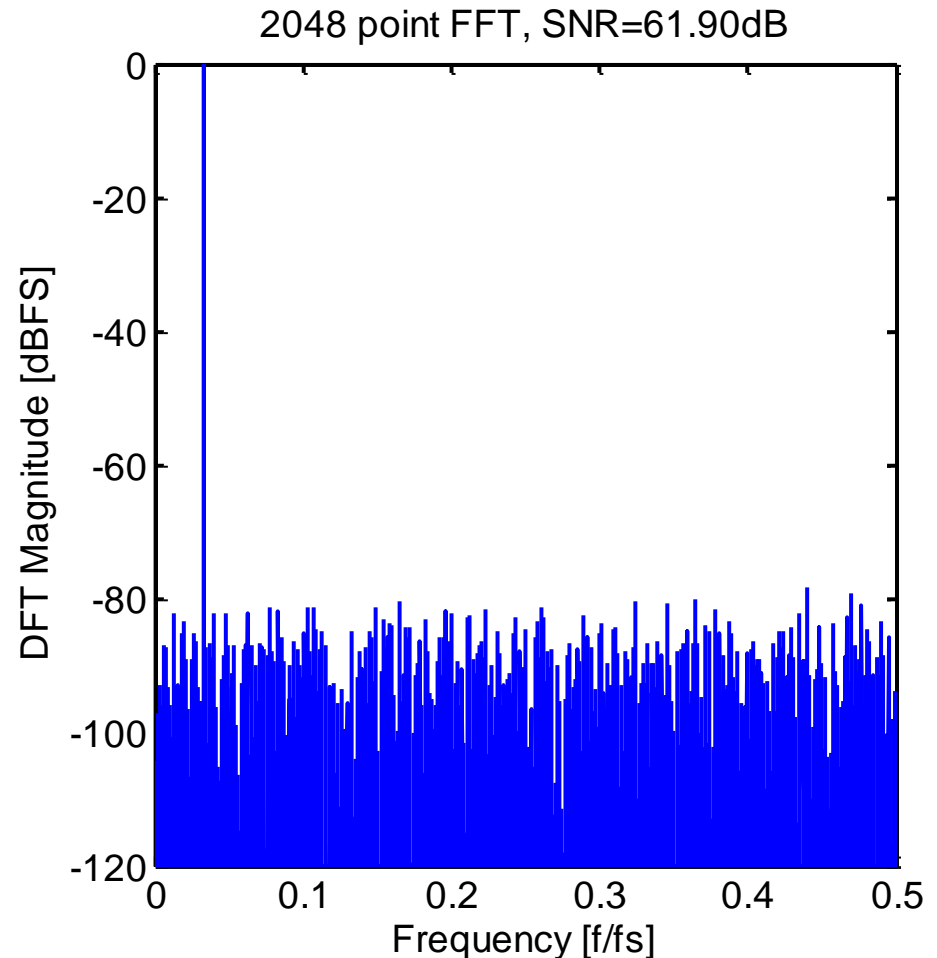
%generate signal, quantize (mid-tread) and take FFT
x = cos(2*pi*fx/fs*[0:N-1]);
x = round(x/LSB)*LSB;
s = abs(fft(x));
s = s(1:end/2)/N*2;

% calculate SNR
sigbin = 1 + cycles;
noise = [s(1:sigbin-1), s(sigbin+1:end)];
snr = 10*log10( s(sigbin)^2/sum(noise.^2) );
```

# Spectrum with Quantization Noise

- 0 dBFS = full-scale sinewave
- Spectrum looks fairly uniform  
*Is this expected?*
- Signal-to-quantization noise ratio equals power in signal bin (just one for coherent sampling), divided by sum of power in all noise bins
- Compare with “theory”:

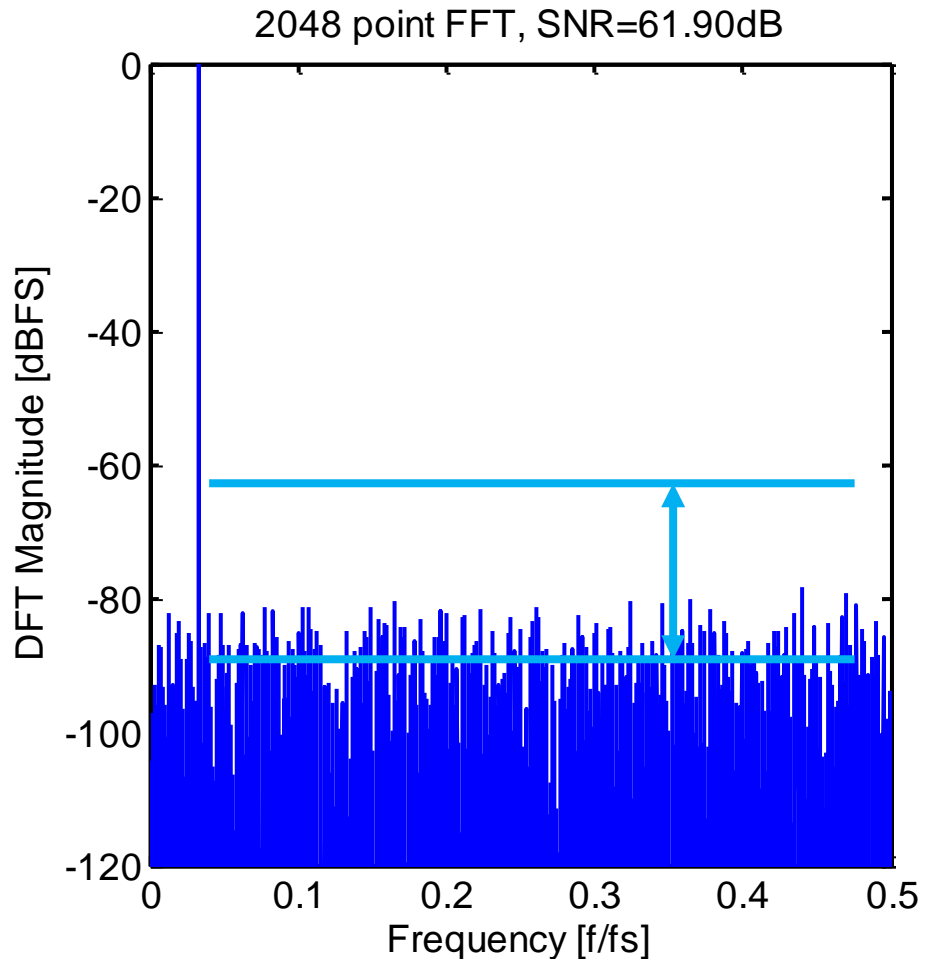
$$\begin{aligned}\text{SQNR} &= \frac{\text{Signal Power}}{\text{Quantization Noise Power}} \\ &= 6.02 \cdot N + 1.76 \text{ [dB]} \\ &= 61.9 \text{ dB}\end{aligned}$$



# FFT Noise Floor

$$\begin{aligned} N_{floor} &= -61.9 \text{ dBc} - 10 \log\left(\frac{2048}{2}\right) \\ &= -61.9 \text{ dBc} - 30.1 \text{ dB} \\ &= -92 \text{ dBc} \end{aligned}$$

- How could we lower the noise floor?
- Depends on FFT size
- Plot is “useless” if FFT size is not specified!



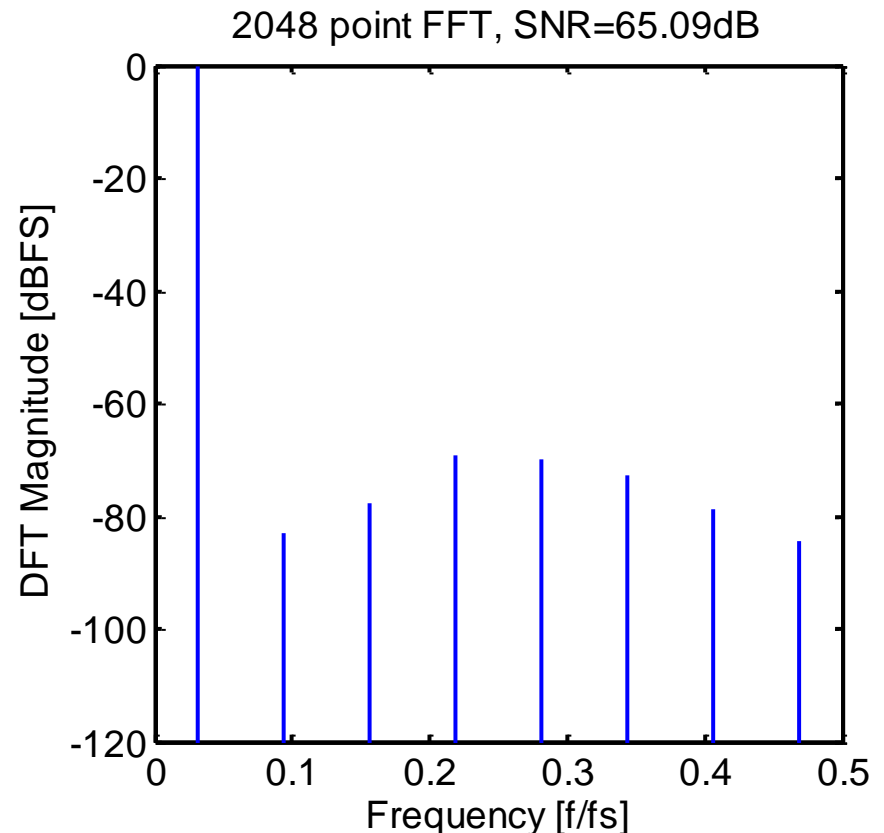
# DFT Plot Annotation

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- DFT plots are fairly meaningless unless you clearly specify the underlying conditions
- Most common annotation
  - Specify how many DFT points were used ( $N$ )
- Less common options
  - Shift DFT noise floor by  $10\log_{10}(N/2)$  dB
  - Normalize with respect to bin width in Hz and express noise as power spectral density
    - "Noise power in 1 Hz bandwidth,,
- DFT should be averaged (e.g. using pwelch in MATLAB)
- Scaling: dBFS vs sinewave power (spectrum analyzer) vs power-spectral density (digital signal processing)

# Periodic Quantization Noise

- Same as before, but cycles = 64 (instead of 67)
- $f_x = f_s \cdot 64 / 2048 = f_s / 32$
- Quantization noise is highly deterministic and periodic
- For more random and "white" quantization noise, it is best to make N and cycles mutually prime
  - $\text{GCD}(N, \text{cycles}) = 1$



# Typical ADC Output Spectrum

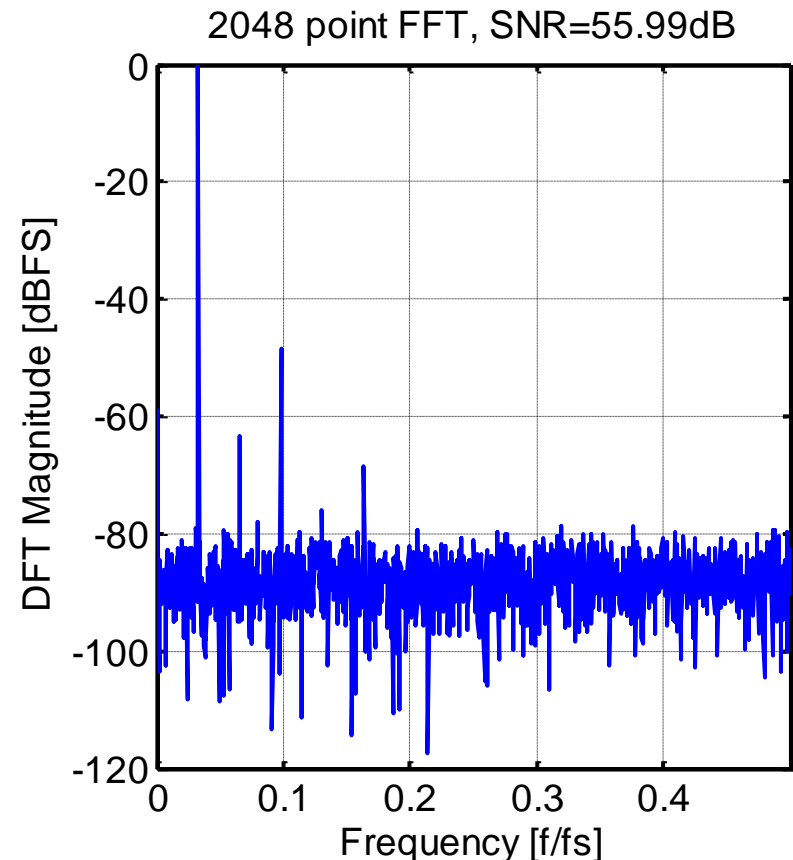
- Fairly uniform noise floor due to additional electronic noise

- Harmonics due to nonlinearities

- Definition of SNR

$$\text{SNR} = \frac{\text{Signal Power}}{\text{Total Noise Power}}$$

- Total noise power includes all bins except DC, signal, and 2<sup>nd</sup> through 7<sup>th</sup> harmonic
  - Both quantization noise and electronic noise affect SNR





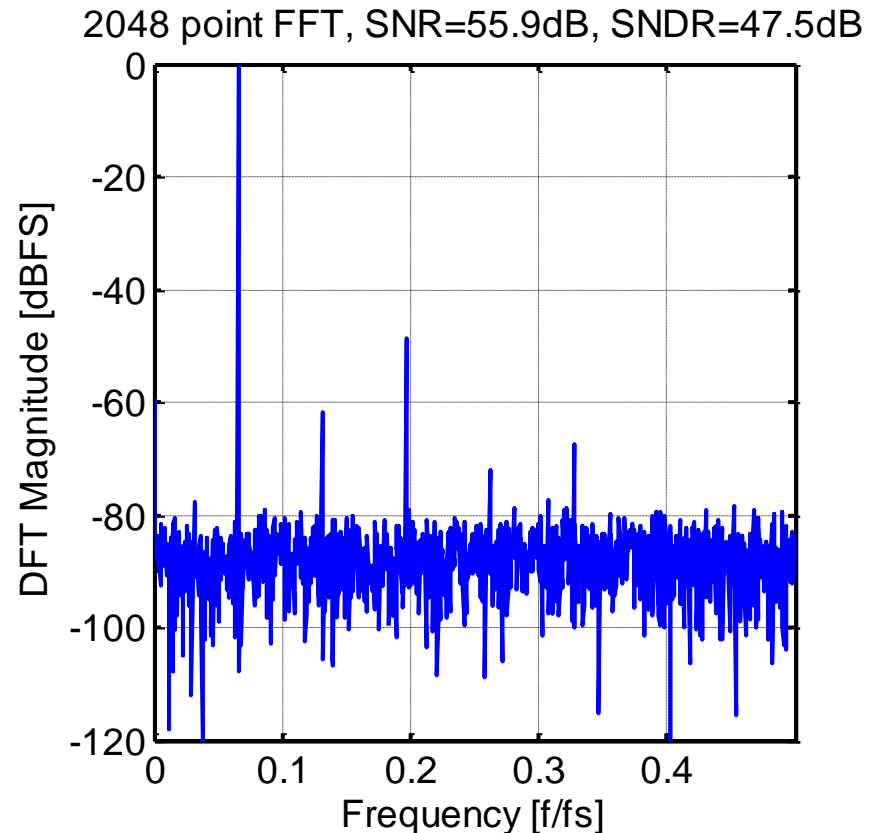
# SNDR and ENOB

- Definition

$$\text{SNDR} = \frac{\text{Signal Power}}{\text{Noise and Distortion Power}}$$

- Noise and distortion power includes all bins except DC and signal
- Effective number of bits

$$\text{ENOB} = \frac{\text{SNDR(dB)} - 1.76\text{dB}}{6.02\text{dB}}$$



# Effective Number of Bits

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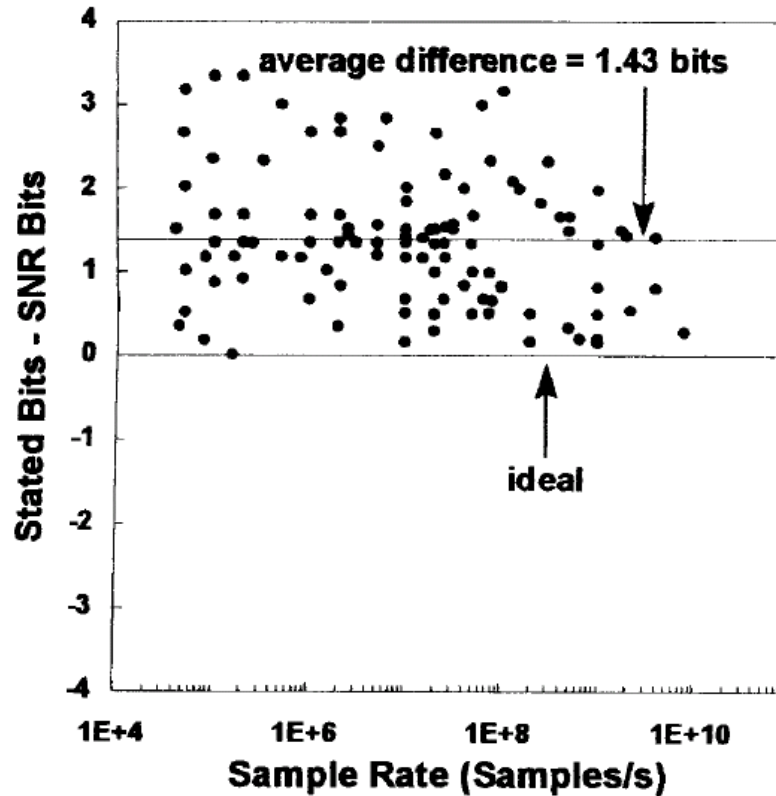
- Is a 10-Bit converter with 47.5dB SNDR really a 10-bit converter?

$$\text{ENOB} = \frac{47.5\text{dB} - 1.76\text{dB}}{6.02\text{dB}} = 7.6$$

- We get ideal ENOB only for zero electronic noise, perfect transfer function with zero INL, ...
- Low electronic noise is costly
  - Cutting thermal noise down by 2x, can cost 4x in power dissipation
- Rule of thumb for good power efficiency:  $\text{ENOB} < B-1$ 
  - B is the "number of wires" coming out of the ADC or the so called "stated resolution"

# Survey Data

$$\text{SNRBits} = \frac{\text{SNR(dB)} - 1.76\text{dB}}{6.02\text{dB}}$$



R. H. Walden, "Analog-to-digital converter survey and analysis," *IEEE J. on Selected Areas in Communications*, pp. 539-50, April 1999

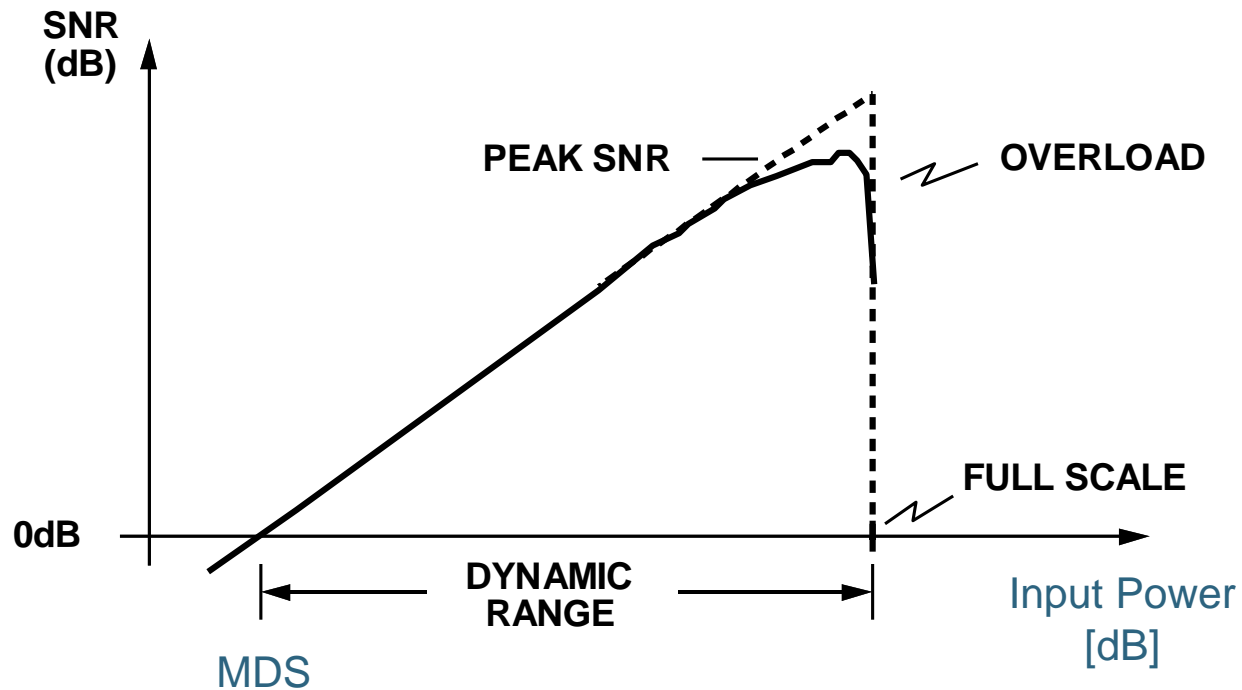
# **EE 240C**

## **Analog-Digital Interface Integrated Circuits**

### **Dynamic Range & Distortion**

# Dynamic Range

$$DR = \frac{\text{Maximum Signal Power}}{\text{Minimum Detectable Signal}} \geq \text{SNR}_{\text{peak}}$$

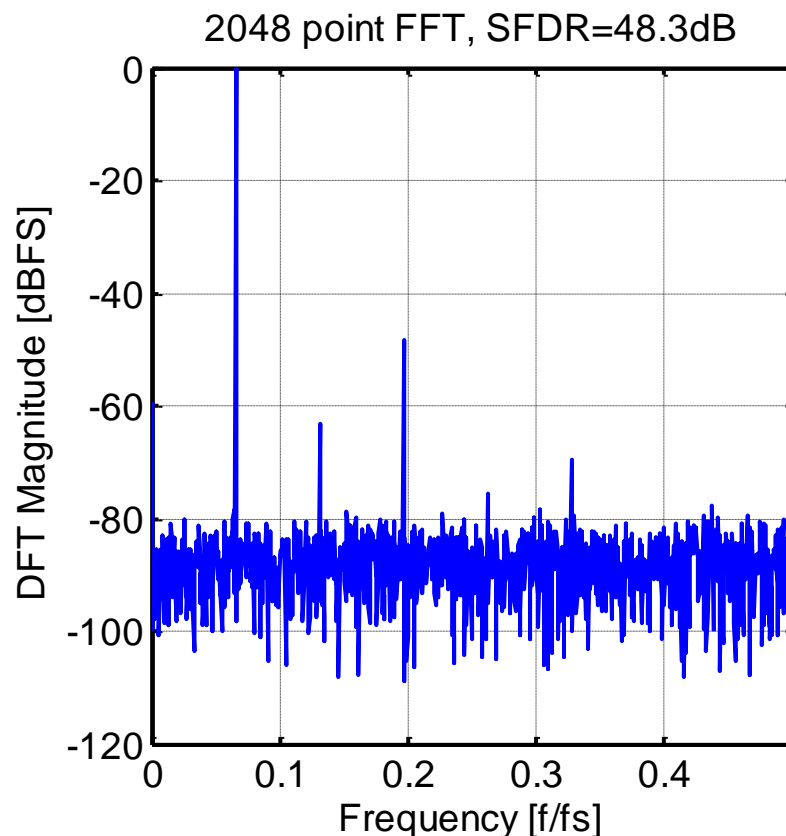


# SFDR

- Definition of "Spurious Free Dynamic Range"

$$\text{SFDR} = \frac{\text{Signal Power}}{\text{Largest Spurious Power}}$$

- Largest spur is often (but not necessarily) a harmonic of the input tone
- SFDR represent smallest value of signal that can be distinguished from large interfering signal



# SDR and THD

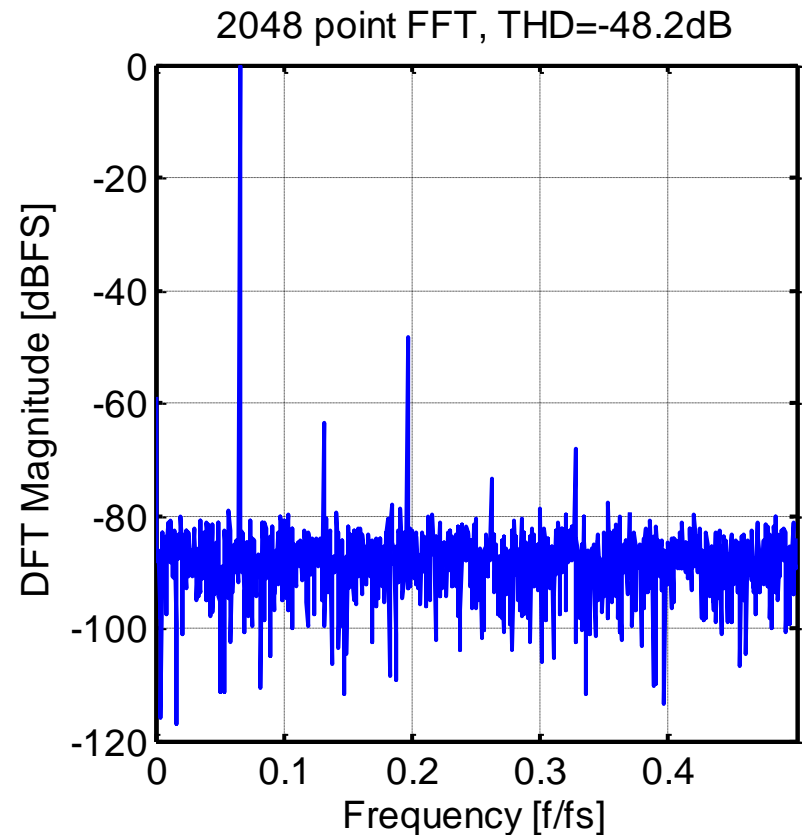
- Signal-to-distortion ratio

$$\text{SDR} = \frac{\text{Signal Power}}{\text{Total Distortion Power}}$$

- Total harmonic distortion

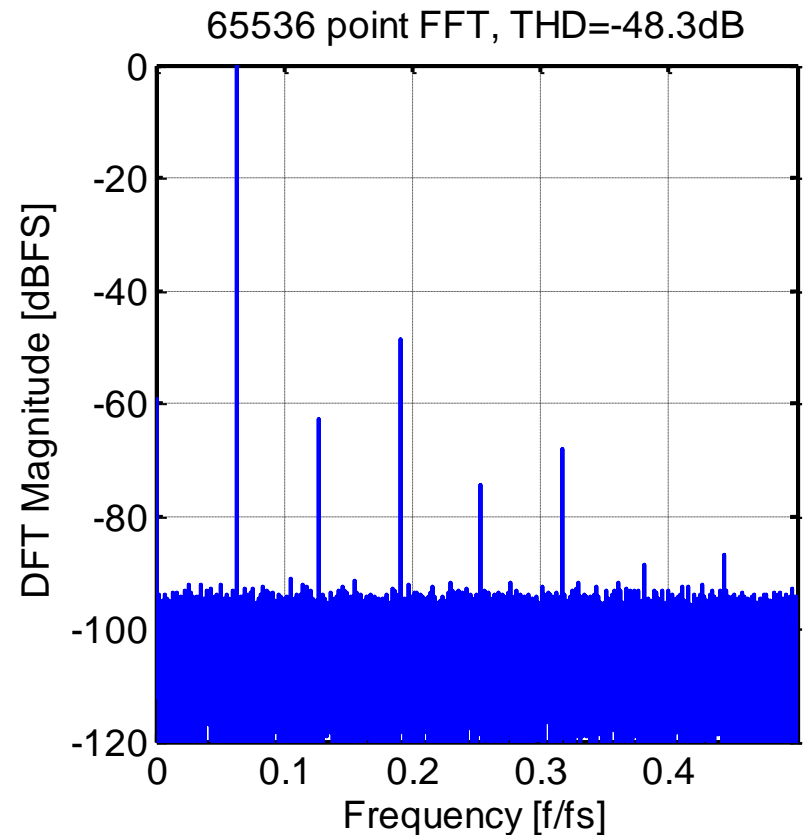
$$\text{THD} = \frac{\text{Total Distortion Power}}{\text{Signal Power}} = \frac{1}{\text{SDR}}$$

- By convention, total distortion power consists of 2<sup>nd</sup> through 7<sup>th</sup> harmonic
- Is there a 6<sup>th</sup> and 7<sup>th</sup> harmonic in the plot to the right?



# Lowering the Noise Floor

- Increasing the FFT size let's us lower the noise floor and reveal low level harmonics





# Aliasing

- Harmonics can appear at "arbitrary" frequencies due to aliasing

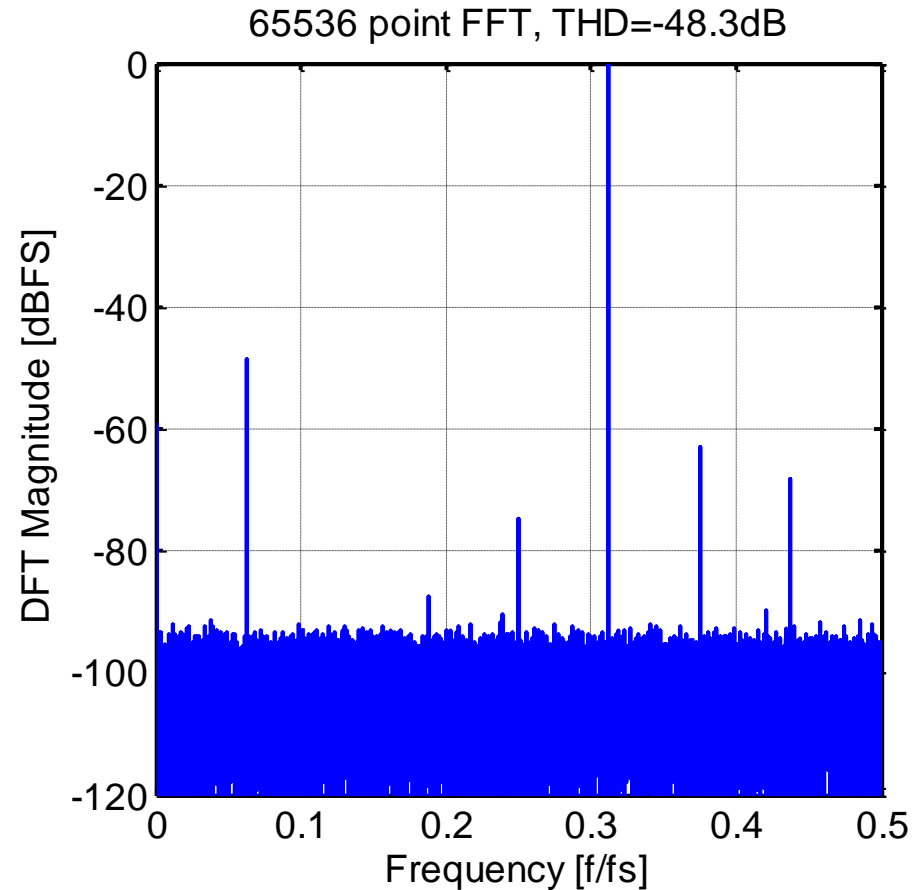
$$f_1 = f_x = 0.3125 f_s$$

$$f_2 = 2 f_1 = 0.6250 f_s \rightarrow 0.3750 f_s$$

$$f_3 = 3 f_1 = 0.9375 f_s \rightarrow 0.0625 f_s$$

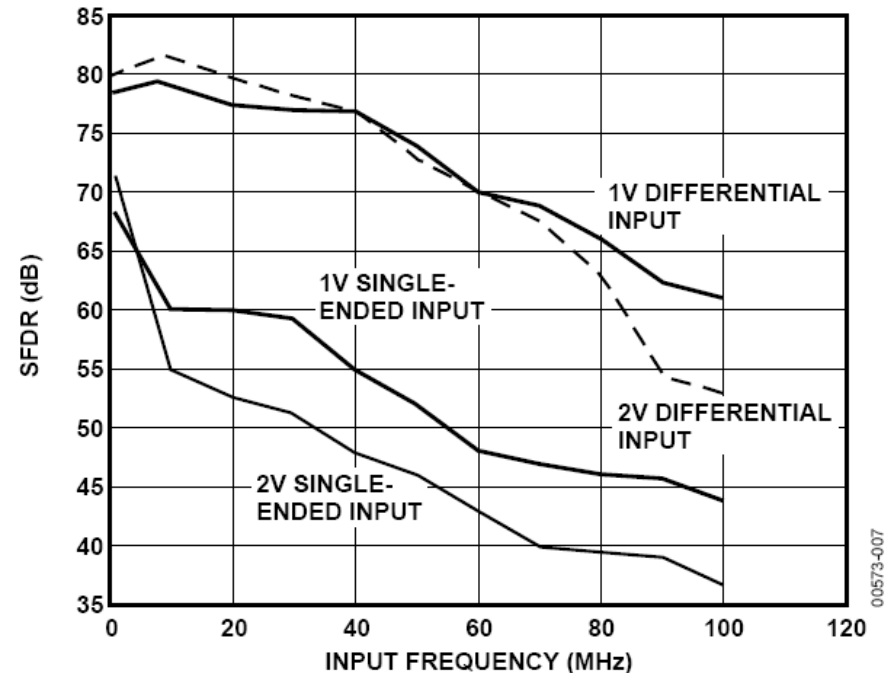
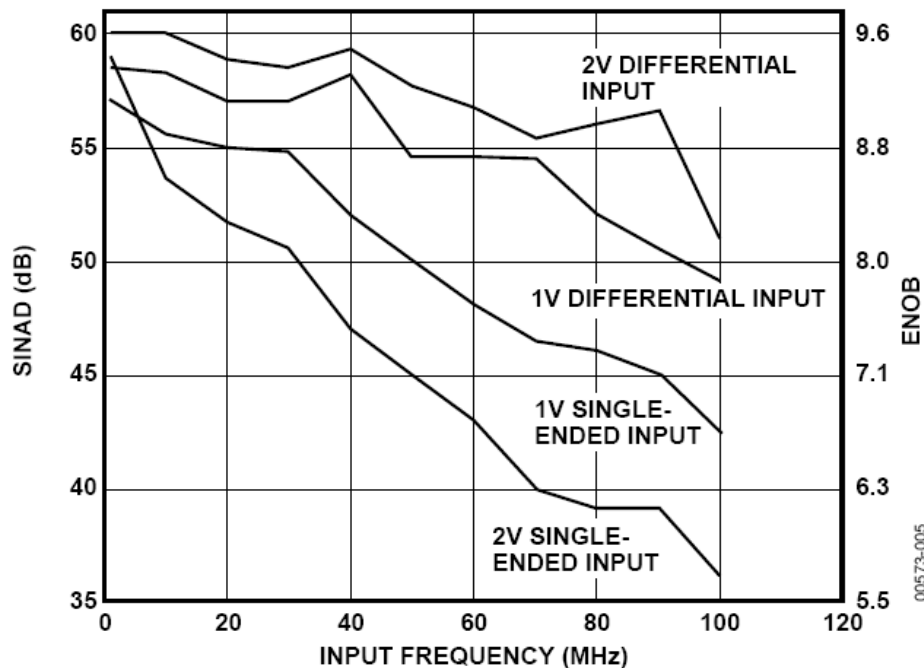
$$f_4 = 4 f_1 = 1.2500 f_s \rightarrow 0.2500 f_s$$

$$f_5 = 5 f_1 = 1.5625 f_s \rightarrow 0.4375 f_s$$



# Frequency Dependence

- Metrics generally depend on frequency
  - Sampling frequency and input frequency



[Analog Devices, AD9203 Datasheet]

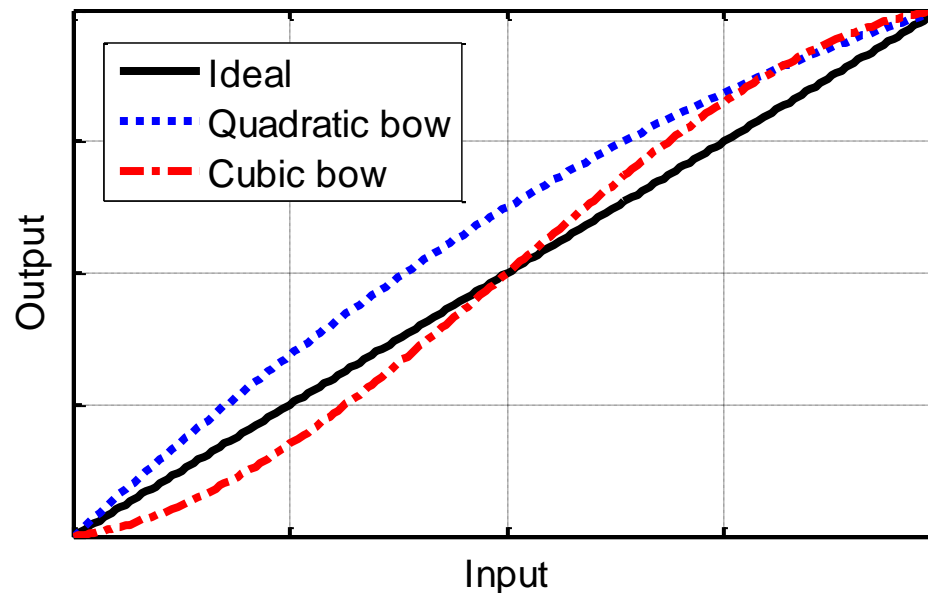
# ERBW

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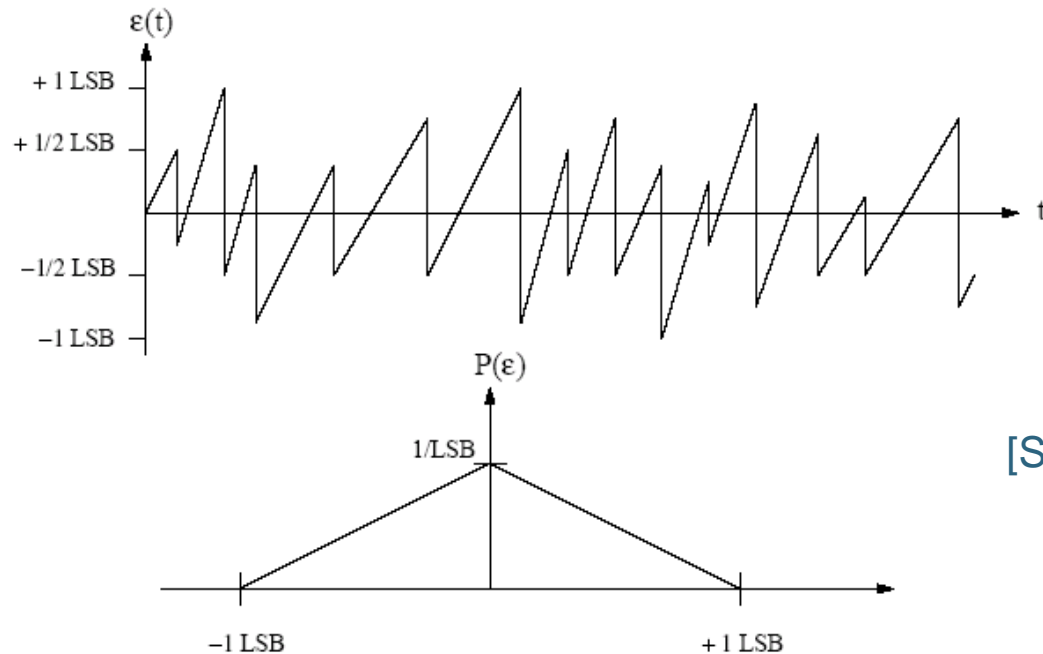
- Defined as the input frequency at which the SNDR of a converter has dropped by 3dB
  - Equivalent to a 0.5-bit loss in ENOB
- $\text{ERBW} > f_s/2$  is not uncommon, especially in converters designed for sub-sampling applications

# Relationship Between INL and SFDR

- At low input frequencies, finite SFDR is mostly due to INL
- Quadratic/cubic bow gives rise to second/third order harmonic
- Rule of thumb:  $\text{SFDR} \cong 20\log(2^B/\text{INL})$ 
  - E.g. 1 LSB INL, 10 bits  $\rightarrow \text{SFDR} \cong 60\text{dB}$



# SNR Degradation due to DNL (1)



[Source: Ion Opris]

- For an ideal quantizer we assumed uniform quantization error over  $\pm\Delta/2$
- Let's add uniform DNL over  $\pm 0.5 \text{ LSB}$  and repeat math...

# SNR Degradation due to DNL (2)

- Integrate triangular pdf

$$\overline{e^2} = 2 \int_0^{+\Delta} \left(1 - \frac{e}{\Delta}\right) \frac{e^2}{\Delta} de = \frac{\Delta^2}{6}$$


$$\Rightarrow \text{SNR} = 6.02 \cdot B - 1.25 \text{ [dB]}$$

- Compare to ideal quantizer

$$\overline{e^2} = \int_{-\Delta/2}^{+\Delta/2} \frac{e^2}{\Delta} de = \frac{\Delta^2}{12}$$

$$\Rightarrow \text{SNR} = 6.02 \cdot B + 1.76 \text{ [dB]}$$

3dB



- Bottom line: non-zero DNL across many codes can easily cost a few dB in SNR
  - "DNL noise"

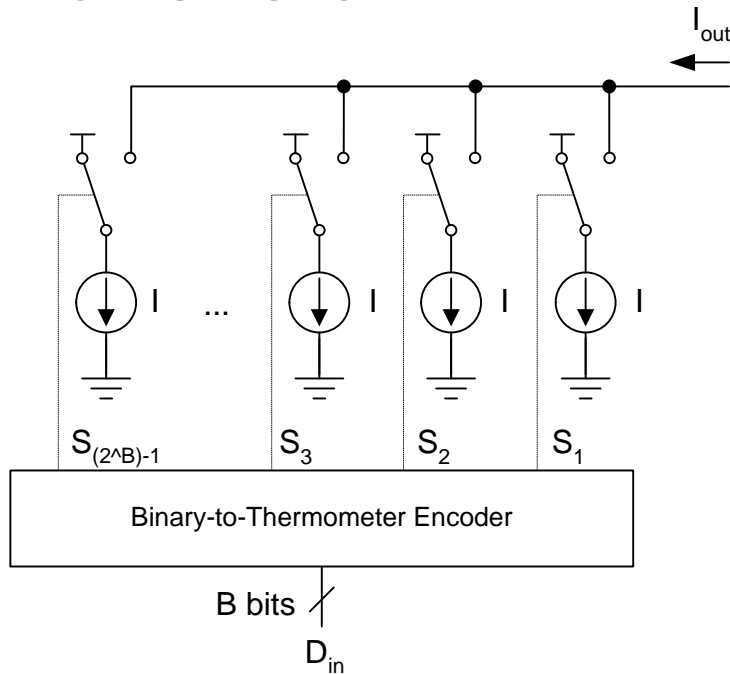
# **EE 240C**

## **Analog-Digital Interface Integrated Circuits**

### **Error Sources**

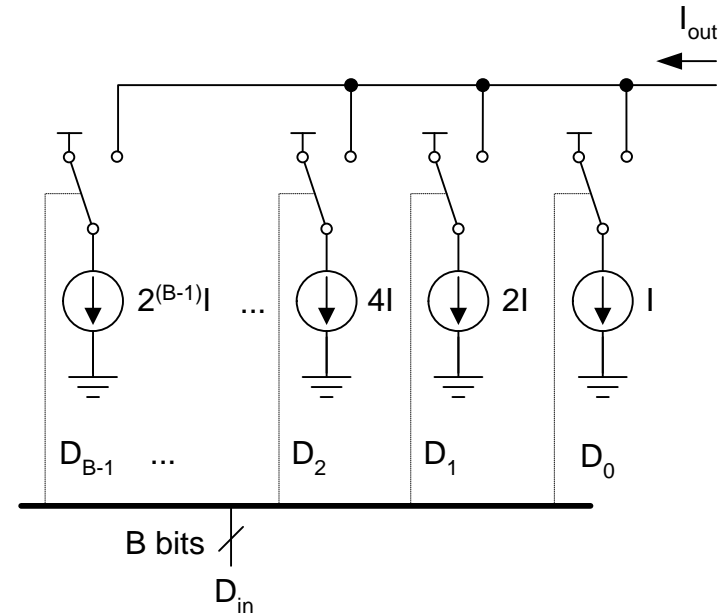
# Motivation: Current DAC (“M-DAC”)

## Unit Element



$2^B-1$  switches

## Binary Weighted



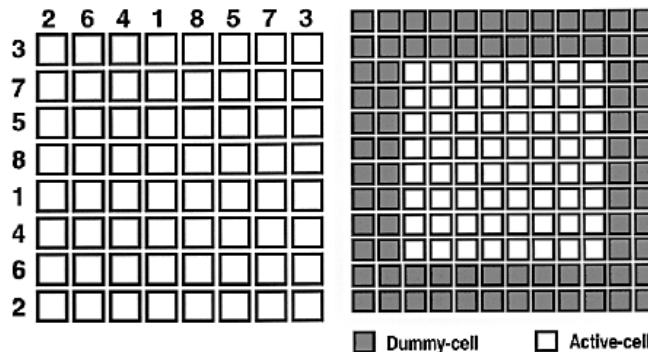
B switches

How do their DNL and INL compare?



# Static Errors – Systematic

- Unit element mismatch cause INL and DNL errors
- Types of errors
  1. Systematic errors
    - Affect all circuits uniformly
    - E.g.
      - Contact and wiring resistance (IR drop)
      - Edge effects, process gradients
      - Finite current source output resistance
    - Can (in theory) be mitigated by proper layout and design



E.g.  
[\[Lin, JSSC 12/98\]](#),  
[\[Van der Plas, JSSC 12/99\]](#)

# Static Errors – Random

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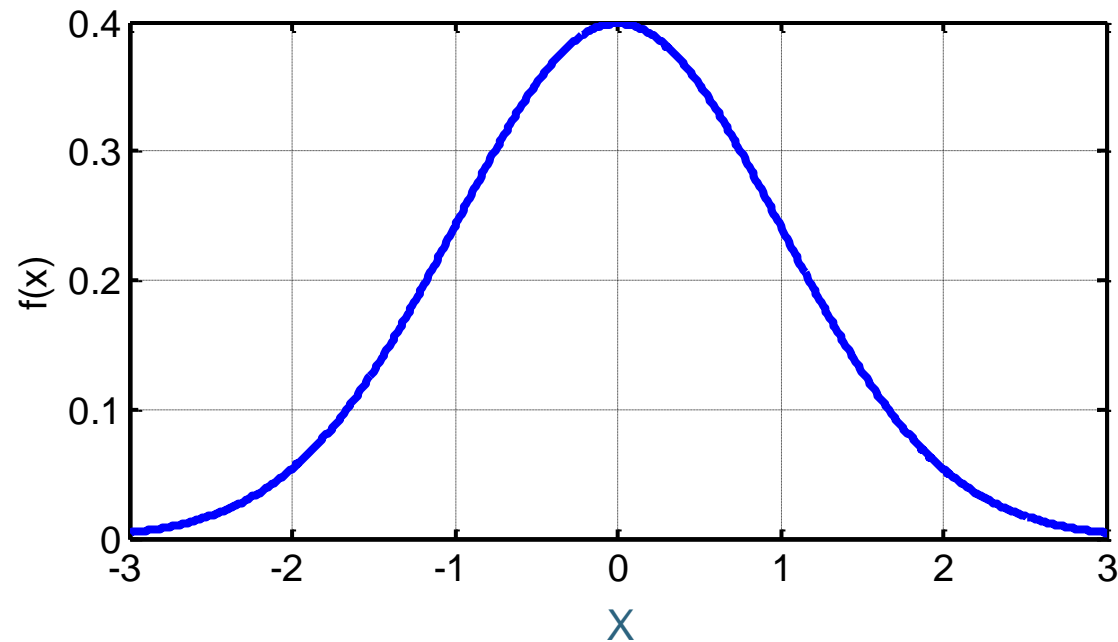
## 2. Random errors

- Vary randomly from device to device
- Caused e.g. by material roughness, randomness in etching, ...
- Usually well approximated by a Gaussian PDF (central limit theorem)
- References
  - C. Conroy et al., “Statistical Design Techniques for D/A Converters,” IEEE J. Solid-State Ckts., pp. 1118–28, Aug. 1989.
  - P. Crippa, et al., "A statistical methodology for the design of high-performance CMOS current-steering digital-to-analog converters," IEEE Trans. CAD of ICs and Syst. pp. 377–394, Apr. 2002.
  - M. J. M. Pelgrom, A. C. J. Duinmaijer, and A. P. G. Welbers, "Matching properties of MOS transistors," *IEEE Journal of Solid-State Circuits*, vol. 24, pp. 1433 – 1439, October 1989.
  - Jeroen A. Croon, Maarten Rosmeulen, Stefaan Decoutere, Willy Sansen, Herman E. Maes; *An easy-to-use mismatch model for the MOS transistor*, IEEE Journal of Solid-State Circuits, vol. 37, pp. 1056 – 1064, August 2002.

# Gaussian Distribution

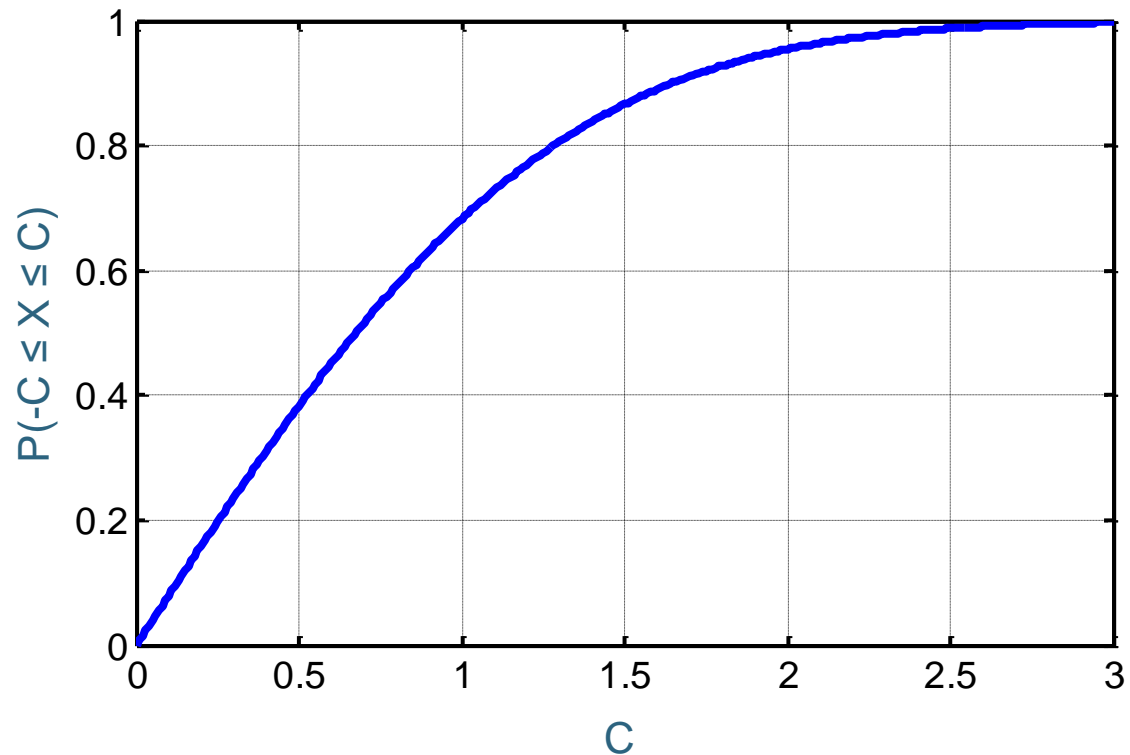
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$$f(x) = \frac{1}{\sqrt{2\pi}\sigma} e^{-\frac{(x-\mu)^2}{2\sigma^2}} \quad X = \frac{x-\mu}{\sigma}$$



# Yield (1)

$$P(-C \leq X \leq +C) = \frac{1}{\sqrt{2\pi}} \int_{-C}^{+C} e^{-\frac{x^2}{2}} dX = \operatorname{erf}\left(\frac{C}{\sqrt{2}}\right)$$



# Yield (2)

---

| C      | $P(-C \leq X \leq C)$ [%] | C      | $P(-C \leq X \leq C)$ [%] |
|--------|---------------------------|--------|---------------------------|
| 0.2000 | 15.8519                   | 2.2000 | 97.2193                   |
| 0.4000 | 31.0843                   | 2.4000 | 98.3605                   |
| 0.6000 | 45.1494                   | 2.6000 | 99.0678                   |
| 0.8000 | 57.6289                   | 2.8000 | 99.4890                   |
| 1.0000 | 68.2689                   | 3.0000 | 99.7300                   |
| 1.2000 | 76.9861                   | 3.2000 | 99.8626                   |
| 1.4000 | 83.8487                   | 3.4000 | 99.9326                   |
| 1.6000 | 89.0401                   | 3.6000 | 99.9682                   |
| 1.8000 | 92.8139                   | 3.8000 | 99.9855                   |
| 2.0000 | 95.4500                   | 4.0000 | 99.9937                   |

# Example

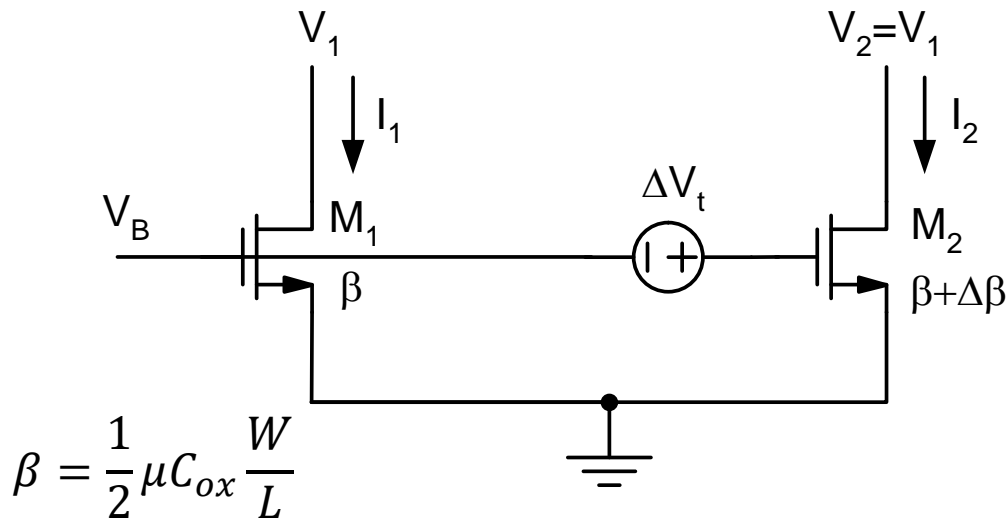
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- Measurements show that the current in a production lot of current sources follows a Gaussian distribution with  $\sigma = 0.1 \text{ mA}$  and  $\mu = 10 \text{ mA}$ 
  - What fraction of current sources is within  $\pm 3\%$  (or  $\pm 1\%$ ) of the mean?
- Relative matching ("coefficient of variation")

$$\sigma_u = \frac{\sigma}{\mu} = \text{stdev}\left(\frac{\Delta I}{I}\right) = \frac{0.1 \text{ mA}}{10 \text{ mA}} = 1\%$$

- Fraction of current sources within 3%
  - $C = 3 \rightarrow 99.73\%$
- Fraction of current sources within 1%
  - $C = 1 \rightarrow 68.27\%$

# Mismatch in MOS Current Sources



$$\Delta I = I_1 - I_2 \cong -g_m \Delta V_t + I_1 \frac{\Delta \beta}{\beta}$$

$$\frac{\Delta I}{I_1} \cong -\frac{g_m}{I_1} \Delta V_t + \frac{\Delta \beta}{\beta}$$

$$\sigma_{\Delta V_t} = \frac{A_{V_t}}{\sqrt{WL}} \quad \sigma_{\frac{\Delta \beta}{\beta}} = \frac{A_{\beta}}{\sqrt{WL}}$$

- Example

- $W=500\mu\text{m}$ ,  $L=0.2\mu\text{m}$ ,  $g_m/I_D=10\text{S/A}$ ,  $A_{V_t}=5\text{mV}-\mu\text{m}$ ,  $A_{\beta}=1\%- \mu\text{m}$

$$\sigma_{\frac{\Delta I}{I_1}} = \sqrt{\left(10 \frac{\text{S}}{\text{A}} \cdot \frac{5\text{mV}}{10}\right)^2 + \left(\frac{1\%}{10}\right)^2} = \sqrt{(0.5\%)^2 + (0.1\%)^2} = 0.51\%$$

# **EE 240C**

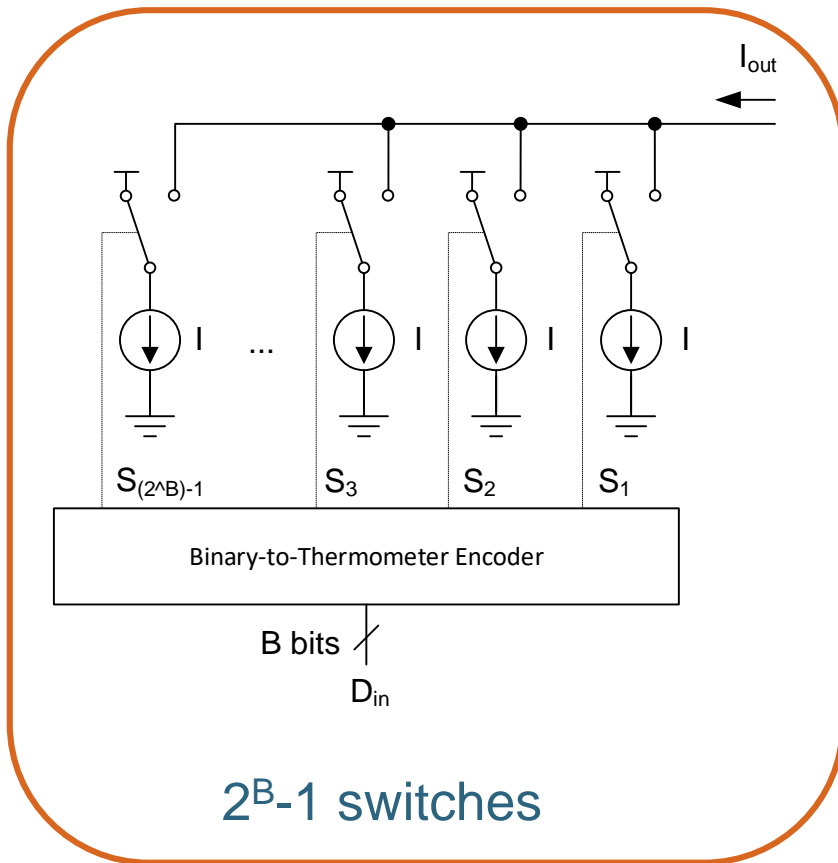
## **Analog-Digital Interface Integrated Circuits**

### **DNL & INL of Unit Element DAC**

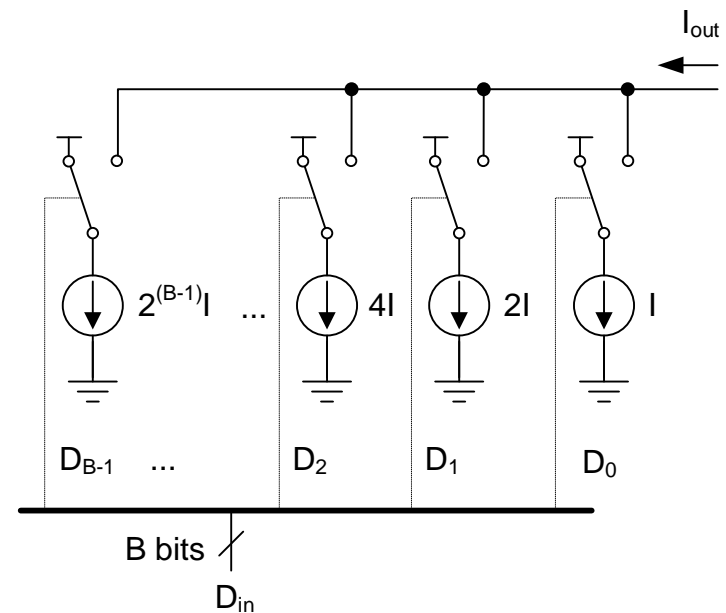


# Unit Element DAC

## Unit Element



## Binary Weighted



# DNL of Unit Element DAC

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$$\text{DNL}(k) = \frac{\text{Step}(k) - \text{Step}_{\text{avg}}}{\text{Step}_{\text{avg}}} = \frac{I_k - \frac{1}{N} \sum_{j=1}^N I_j}{\frac{1}{N} \sum_{j=1}^N I_j} \cong \frac{I_k - I}{I} = \frac{\Delta I}{I}$$
$$\text{stdev}(\text{DNL}(k)) = \text{stdev}\left(\frac{\Delta I}{I}\right) = \sigma_u$$

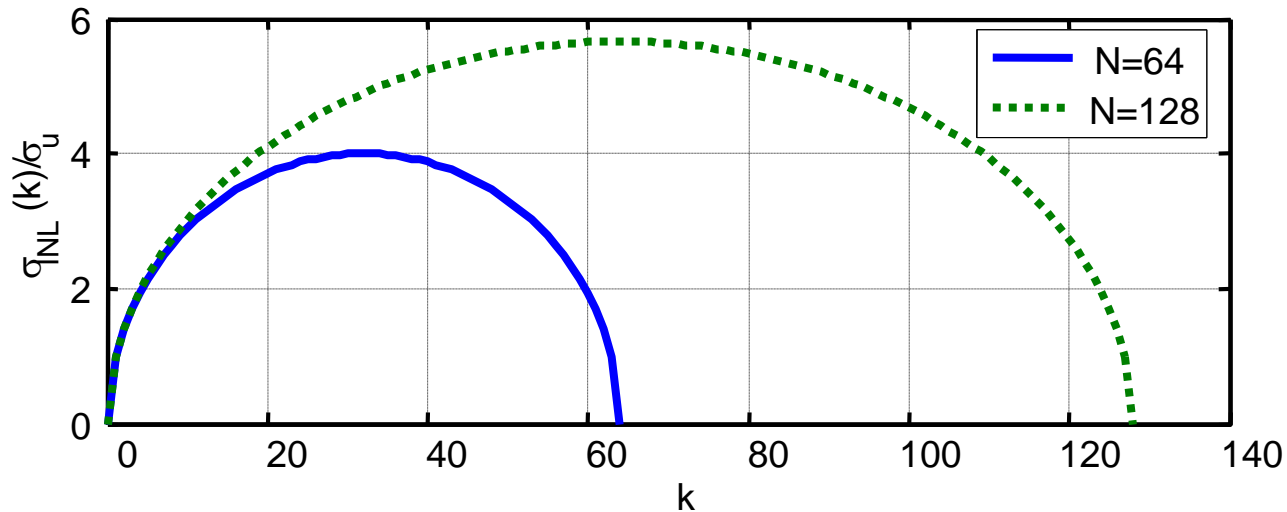
- Standard deviation of DNL for each code is simply equal to relative matching ( $\sigma_u$ ) of unit elements
- Example
  - Say we have unit elements with  $\sigma_u = 1\%$  and want 99.73% of all converters to meet the spec
  - Which DNL specification value should go into the datasheet?

# DNL Yield Example

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- First cut solution
  - For 99.73% yield, need  $C = 3$
  - $\sigma_{\text{DNL}} = \sigma_u = 1\%$
  - $3 \sigma_{\text{DNL}} = 3\%$
  - DNL specification for a yield of 99.73% is  $\pm 0.03$  LSB
    - Independent of target resolution (?)
- Not quite right
  - Must keep in mind that a converter will meet specs only if all codes meet DNL spec, i.e.  $\text{DNL}(k) < \text{DNL}_{\text{spec}}$  for all  $k$
  - A converter with more codes is less likely to have all codes meet the specification
  - E.g. for 12-Bit DAC, DNL spec should be  $\pm 0.0497$  LSB
  - In practice: also affected by correlations  $\rightarrow$  use (Monte Carlo) simulation & measurements

# INL



- Standard deviation of INL is maximum at mid-scale ( $k=N/2$ )

$$\sigma_{\text{INL}} \cong \sigma_u \sqrt{\frac{N}{2} \left(1 - \frac{N/2}{N}\right)} = \frac{1}{2} \sigma_u \sqrt{N} \cong \frac{1}{2} \sigma_u \sqrt{2^B}$$

- For derivation of this result see  
[\[Kuboki et al., IEEE Trans. Circuits & Systems, 6/1982\]](#)

# Maximum Achievable Resolution for INL

---

$$B \cong \log_2 \left( 4 \left[ \frac{\sigma_{\text{INL}}}{\sigma_u} \right]^2 \right) = 2 + 2 \log_2 \left( \frac{\sigma_{\text{INL}}}{\sigma_u} \right)$$

- Example:  $\sigma_{\text{INL}} = 0.1$  LSB (at mid-scale code)

| $\sigma_u$ | <b>B</b> |
|------------|----------|
| 1%         | 8.6      |
| 0.5%       | 10.6     |
| 0.2%       | 13.3     |
| 0.1%       | 15.3     |

# INL Yield

---

- Again, we should ask how many DACs will meet the spec for a given  $\sigma_{\text{INL}}$  (worst code)
  - It turns out that this is a difficult math problem
- Two solutions
  - Do the math
    - G. I. Radulov et al., "Brownian-Bridge-Based Statistical Analysis of the DAC INL Caused by Current Mismatch," IEEE TCAS II, pp. 146–150, Feb. 2007.
  - Yield simulations
- Good rule of thumb
  - For high target yield (>95%), the probability of "all codes meet INL spec" is very close to "worst code meets INL spec"

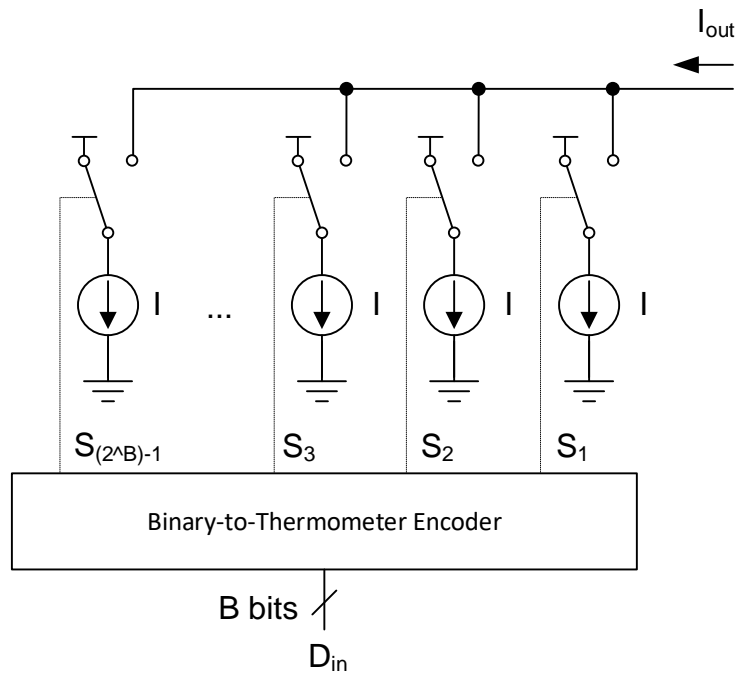
# **EE 240C**

## **Analog-Digital Interface Integrated Circuits**

### **DNL & INL of Binary Weighted DAC**

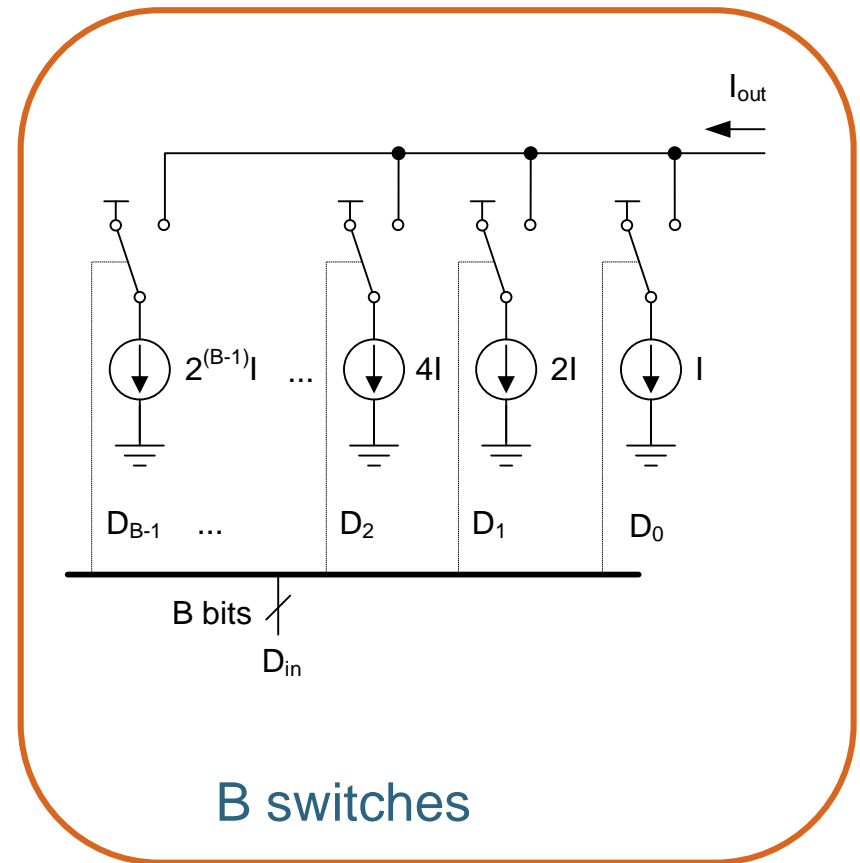
# Unit Element DAC

## Unit Element



$2^B-1$  switches

## Binary Weighted



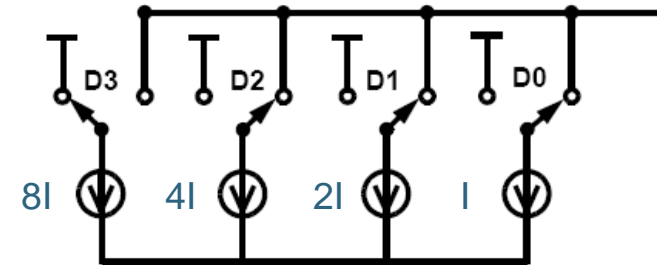
B switches



# DNL/INL of Binary Weighted DAC

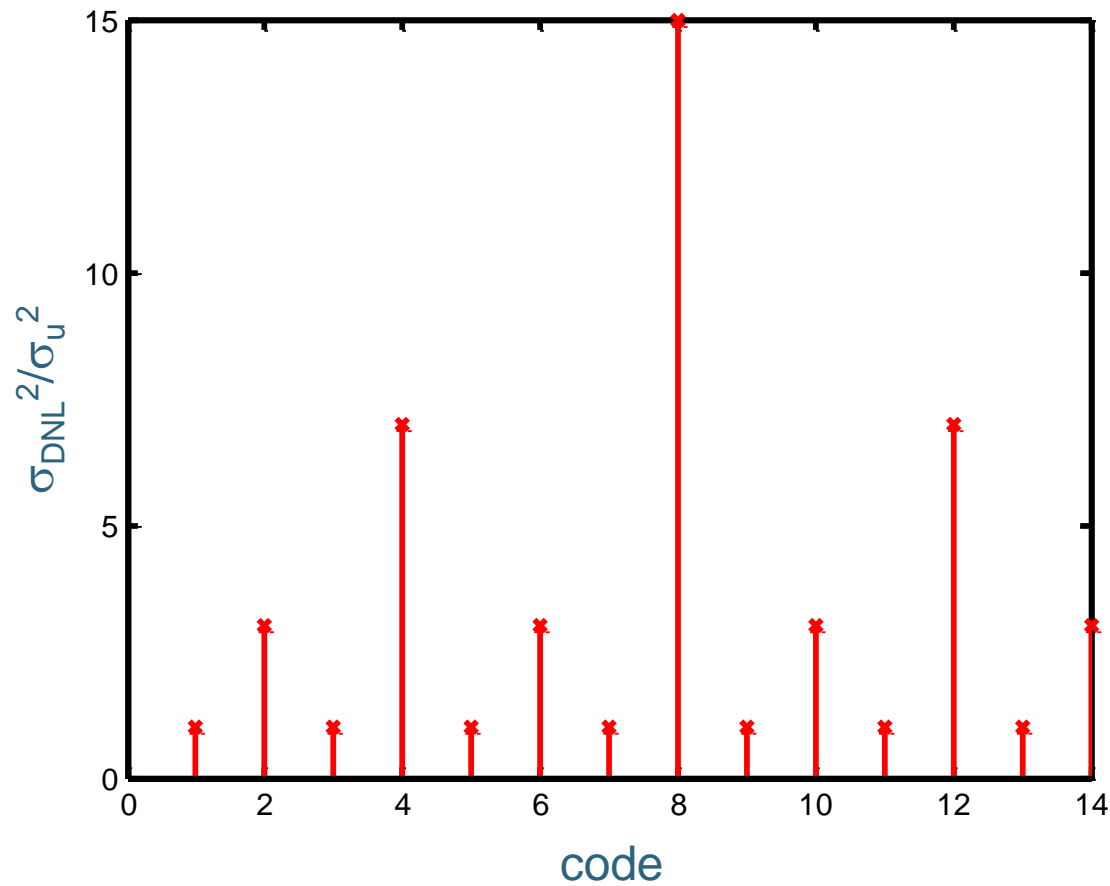
- INL same as for thermometer DAC
  - Why?
- DNL is not same for all codes, but depends on transition
- Consider worst case: 0111 ...  $\rightarrow$  1000 ...
  - Turning on MSB and turning off all LSBs

$$\sigma_{DNL}^2 = \underbrace{(2^{B-1} - 1)\sigma_u^2}_{0111\dots} + \underbrace{(2^{B-1})\sigma_u^2}_{1000\dots} = (2^B - 1)\sigma_u^2$$

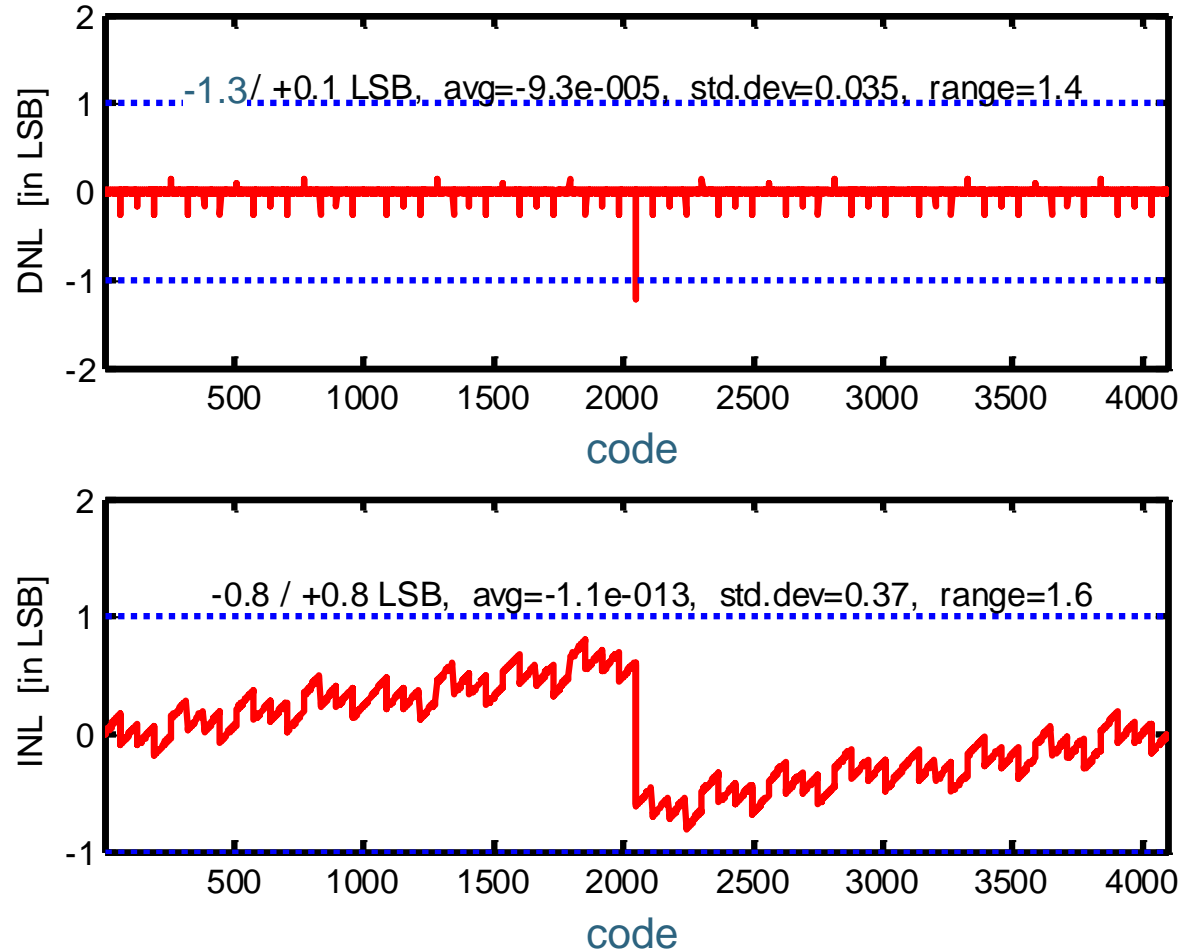


- Example
  - $B = 12$ ,  $\sigma_u = 1\%$   $\rightarrow \sigma_{DNL} = 0.64$  LSB
  - Much worse than thermometer DAC

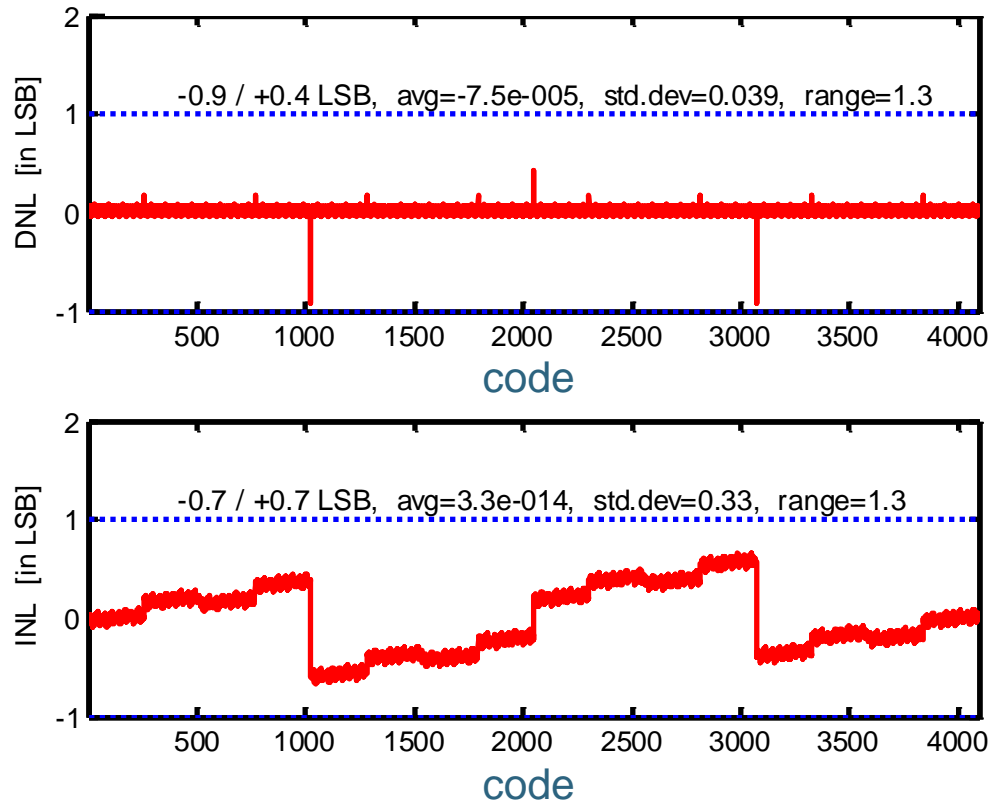
# $\sigma_{\text{DNL}}$ (4-bit Example)



# Simulation Example



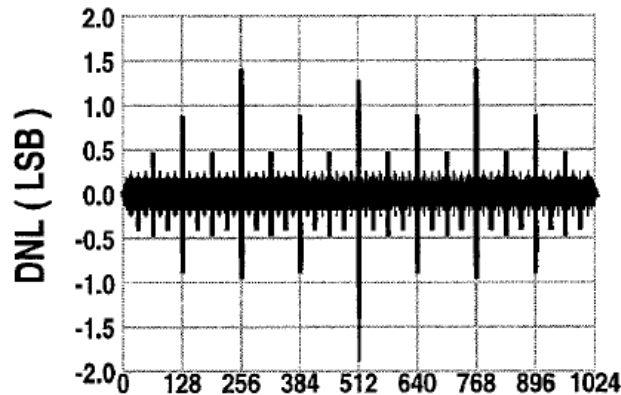
# Another Random Run



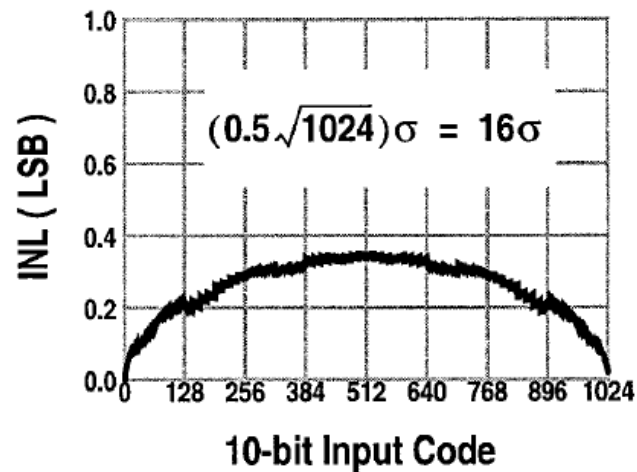
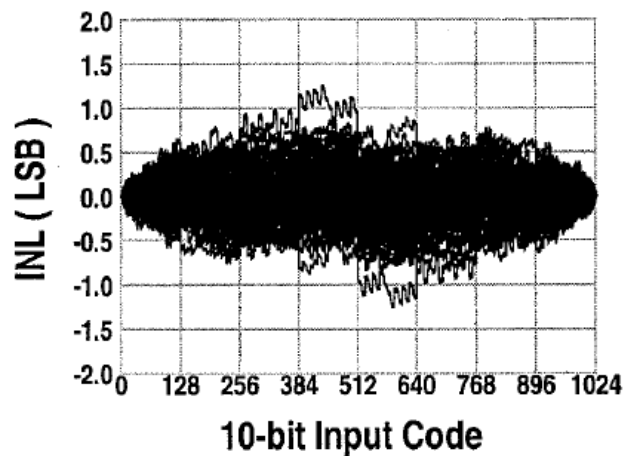
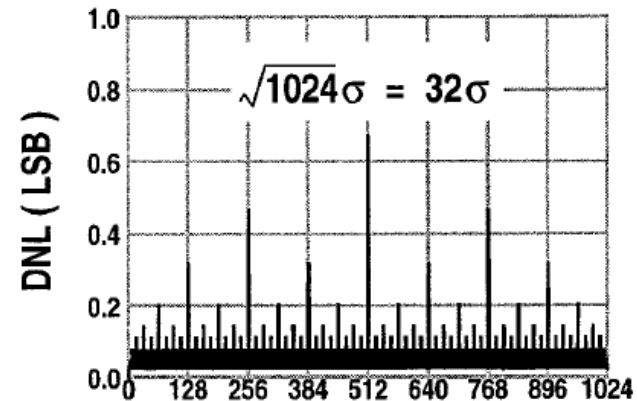
- Peak DNL not at mid-scale!
  - Important to realize that this is just one single statistical outcome...

# Multiple Simulation Runs (100)

Overlay Plot



RMS DNL and INL



[Lin & Bult, JSSC 12/1998]

# **EE 240C**

## **Analog-Digital Interface Integrated Circuits**

### **Segmented DAC**

# Comparison

|                                       | Unit<br>Element                         | Compromise? | Binary<br>Weighted              |
|---------------------------------------|---|-------------|---------------------------------|
| $\sigma_{\text{INL}}$<br>(worst case) | $\cong \frac{1}{2} \sigma_u \sqrt{2^B}$ |             |                                 |
| $\sigma_{\text{DNL}}$<br>(worst case) | $\cong \sigma_u$                        | ?           | $\cong \sigma_u \sqrt{2^B - 1}$ |
| Number of<br>Switched<br>Elements     | $2^B - 1$                               | ?           | $B$                             |

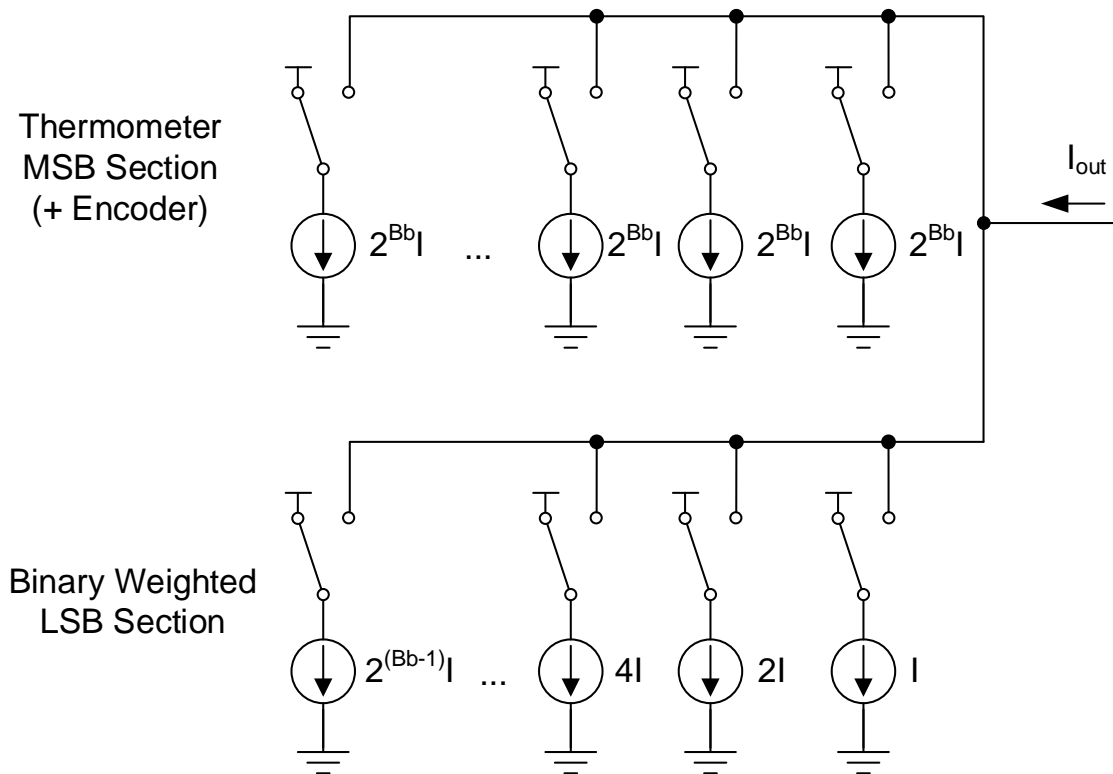
# Example ( $B=16$ , $\sigma_u=0.5\%$ )

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| DAC Architecture | $\sigma_{\text{INL}}$<br>(worst) | $\sigma_{\text{DNL}}$<br>(worst) | Number of<br>Switched<br>Elements |
|------------------|----------------------------------|----------------------------------|-----------------------------------|
| Unit Element     | 0.64                             | 0.005                            | 65535                             |
| Binary Weighted  | 0.64                             | 1.28                             | 16                                |
| Compromise?      | ?                                | ?                                | ?                                 |

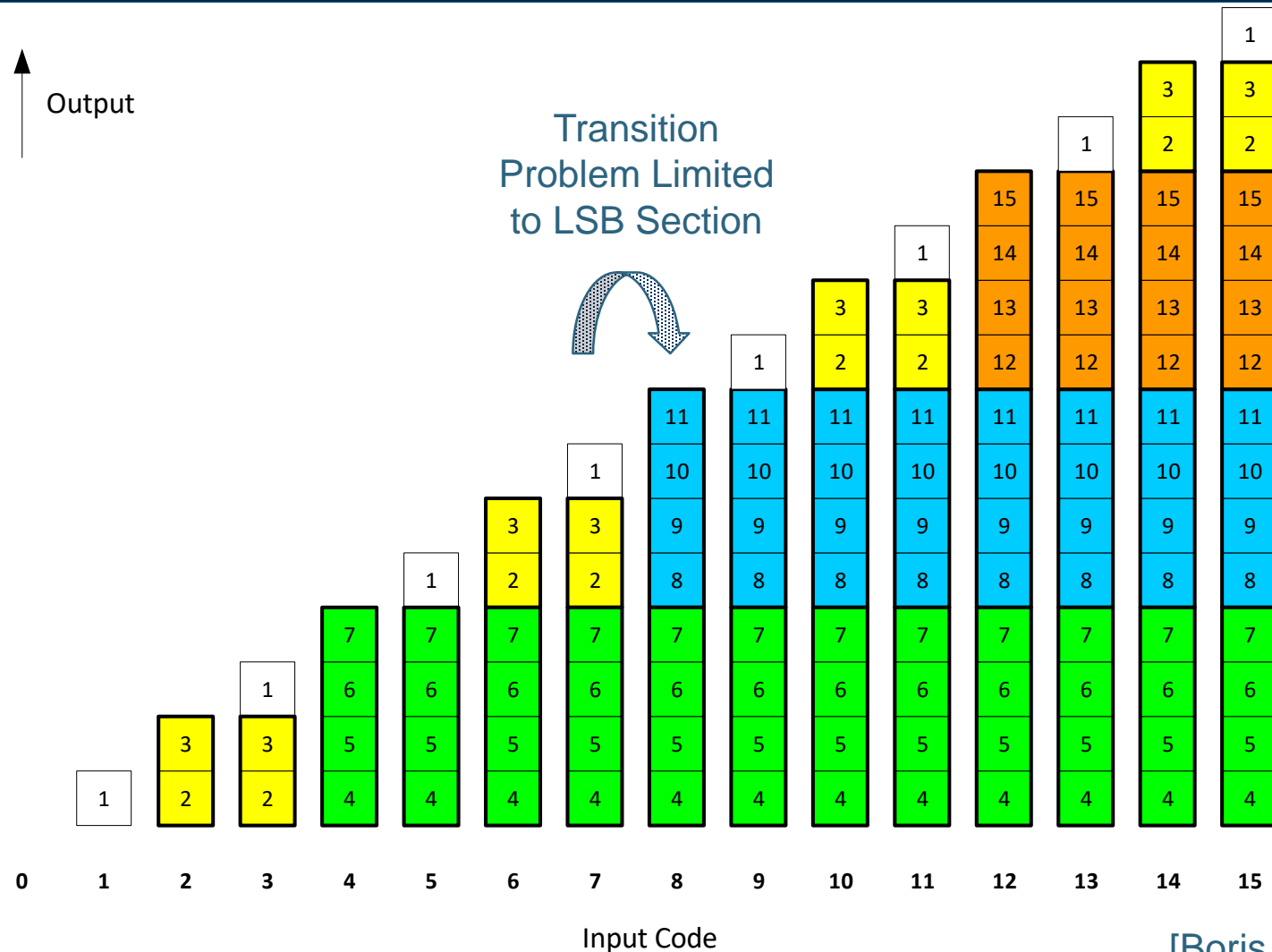


# Segmented DAC



- Binary weighted section with  $B_b$  bits
- Thermometer section with  $B_t = B - B_b$  bits
- Typically  $B_t \sim 4 \dots 8$
- Reasonably small encoder
- Easier to achieve monotonicity

# Segmented DAC (2-2)



[Boris Murmann]

# Comparison

|                                       | Thermometer                             | Segmented                             | Binary Weighted                 |
|---------------------------------------|---|---------------------------------------|---------------------------------|
| $\sigma_{\text{INL}}$<br>(worst case) | $\cong \frac{1}{2} \sigma_u \sqrt{2^B}$ |                                       |                                 |
| $\sigma_{\text{DNL}}$<br>(worst case) | $\cong \sigma_u$                        | $\cong \sigma_u \sqrt{2^{B_b+1} - 1}$ | $\cong \sigma_u \sqrt{2^B - 1}$ |
| Number of Switched Elements           | $2^B - 1$                               | $B_b + 2^{B_t} - 1$                   | $B$                             |

## Example ( $B=12$ , $\sigma_u=1\%$ )

| DAC Architecture                | $\sigma_{\text{INL}}$<br>(worst) | $\sigma_{\text{DNL}}$<br>(worst) | Number of<br>Switched<br>Elements |
|---------------------------------|----------------------------------|----------------------------------|-----------------------------------|
| Thermometer                     | 0.32                             | 0.01                             | 4095                              |
| Binary Weighted                 | 0.32                             | 0.64                             | 12                                |
| Segmented ( $B_b=7$ , $B_t=5$ ) | 0.32                             | 0.16                             | 38                                |

# **EE 240C**

## **Analog-Digital Interface Integrated Circuits**

### **Dynamic DAC Errors**

# Dynamic DAC Errors (1)

---

- Finite settling time and slewing
  - Finite RC time constant
  - Signal dependent slewing
- Feedthrough
  - Coupling from switch signals to DAC output
  - Clock feedthrough
- Glitches due to timing errors
  - Current sources won't switch simultaneously

# Dynamic DAC Errors (2)

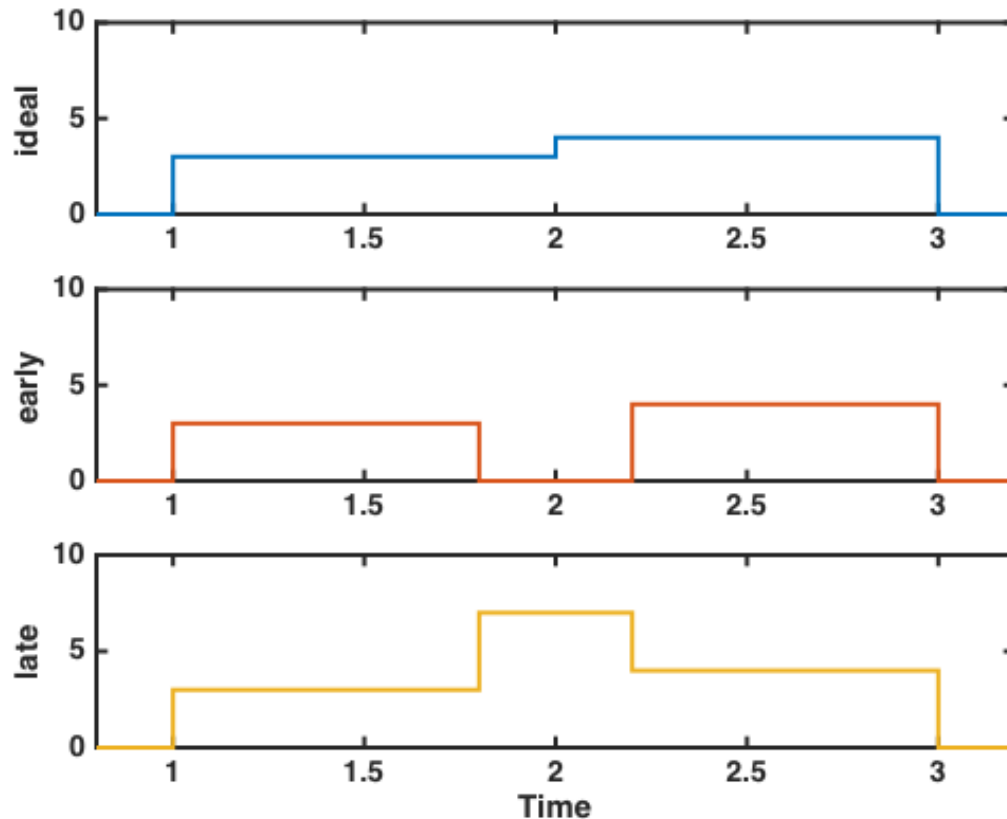
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- References

- Gustavsson, Chapter 12
- M. Albiol, J.L. Gonzalez, E. Alarcon, "Mismatch and dynamic modeling of current sources in current-steering CMOS D/A converters," IEEE TCAS I, pp. 159–169, Jan. 2004
- Doris, van Roermund, Leenaerts, Wide-Bandwidth High Dynamic Range D/A Converters, Springer 2006.
- T. Chen and G.G.E. Gielen, "The analysis and improvement of a current-steering DAC's dynamic SFDR," IEEE Trans. Ckts. Syst. I, pp. 3–15, Jan. 2006.

# Glitch Impulse (1)

- DAC output waveform depends on timing
  - Consider binary weighted DAC transition  $0111... \rightarrow 1000...$



Ideal

LSBs early, MSB late

LSBs late, MSB early



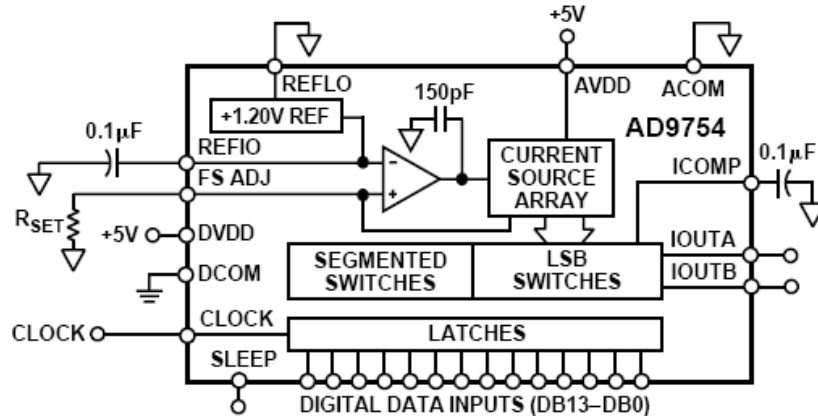
# Glitch Impulse (2)

- Worst case glitch impulse (area):  $\propto \Delta t 2^{B-1}$
- LSB area:  $\propto T$
- Need  $\Delta t 2^{B-1} \ll T$  which implies  $\Delta t \ll T/2^{-B+1}$

| $f_s$ [MHz] | B  | $\Delta t$ [ps] |
|-------------|----|-----------------|
| 1           | 12 | $\ll 488$       |
| 20          | 16 | $\ll 1.5$       |
| 1000        | 10 | $\ll 2$         |

- Need low jitter clock & distribution

# Commercial Example



**AD9754**

**DYNAMIC SPECIFICATIONS** ( $T_{MIN}$  to  $T_{MAX}$ ,  $AVDD = +5V$ ,  $DVDD = +5V$ ,  $I_{OUTFS} = 20mA$ , Differential Transformer Coupled Output,  $50\Omega$  Doubly Terminated, unless otherwise noted)

| Parameter  | Min | Typ | Max | Units          |
|--|-----|-----|-----|----------------|
| <b>DYNAMIC PERFORMANCE</b>                               |     |     |     |                |
| Maximum Output Update Rate ( $f_{CLOCK}$ )               | 125 |     |     | MSPS           |
| Output Settling Time ( $t_{ST}$ ) (to 0.1%) <sup>1</sup> |     | 35  |     | ns             |
| Output Propagation Delay ( $t_{PD}$ )                    |     | 1   |     | ns             |
| Glitch Impulse   |     | 5   |     | pV-s           |
| Output Rise Time (10% to 90%) <sup>1</sup>               |     | 2.5 |     | ns             |
| Output Fall Time (10% to 90%) <sup>1</sup>               |     | 2.5 |     | ns             |
| Output Noise ( $I_{OUTFS} = 20mA$ )                      |     | 50  |     | $pA/\sqrt{Hz}$ |
| Output Noise ( $I_{OUTFS} = 2mA$ )                       |     | 30  |     | $pA/\sqrt{Hz}$ |

# **EE 240C**

## **Analog-Digital Interface Integrated Circuits**

### **DAC Implementation**

# Implementation Example

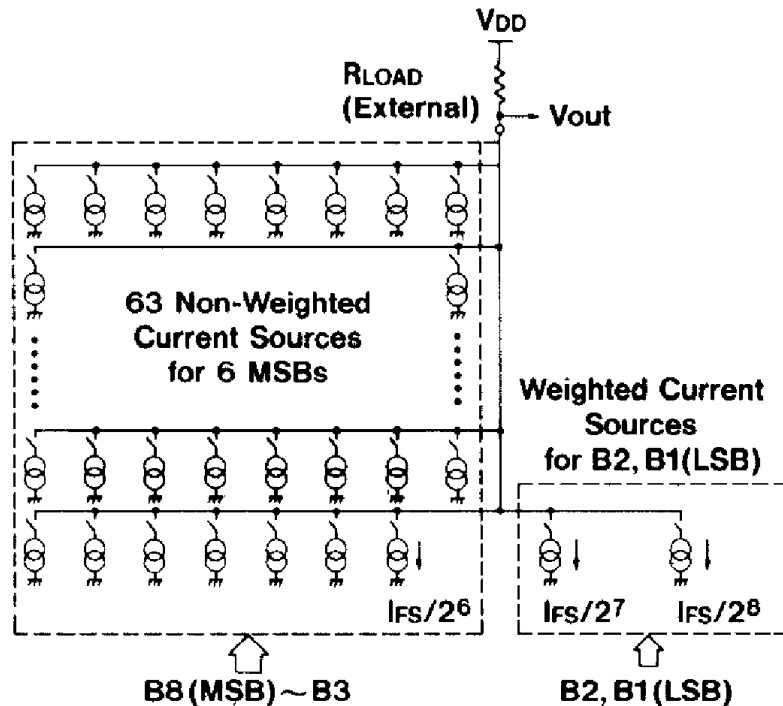


Fig. 1. Basic architecture of the DAC.

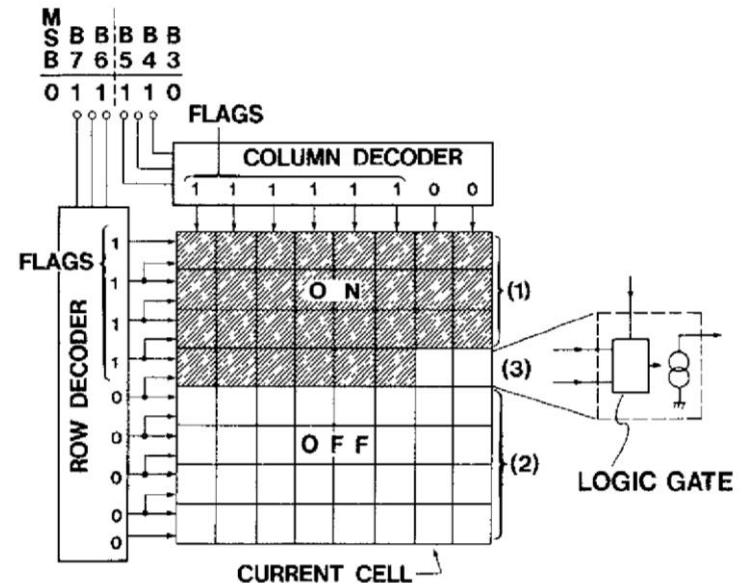
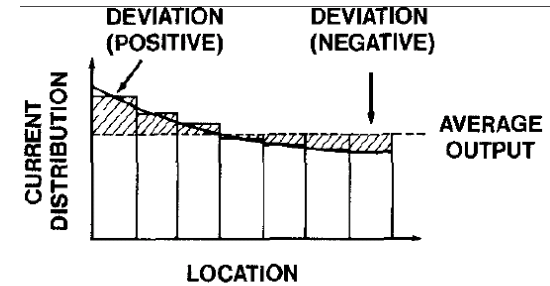
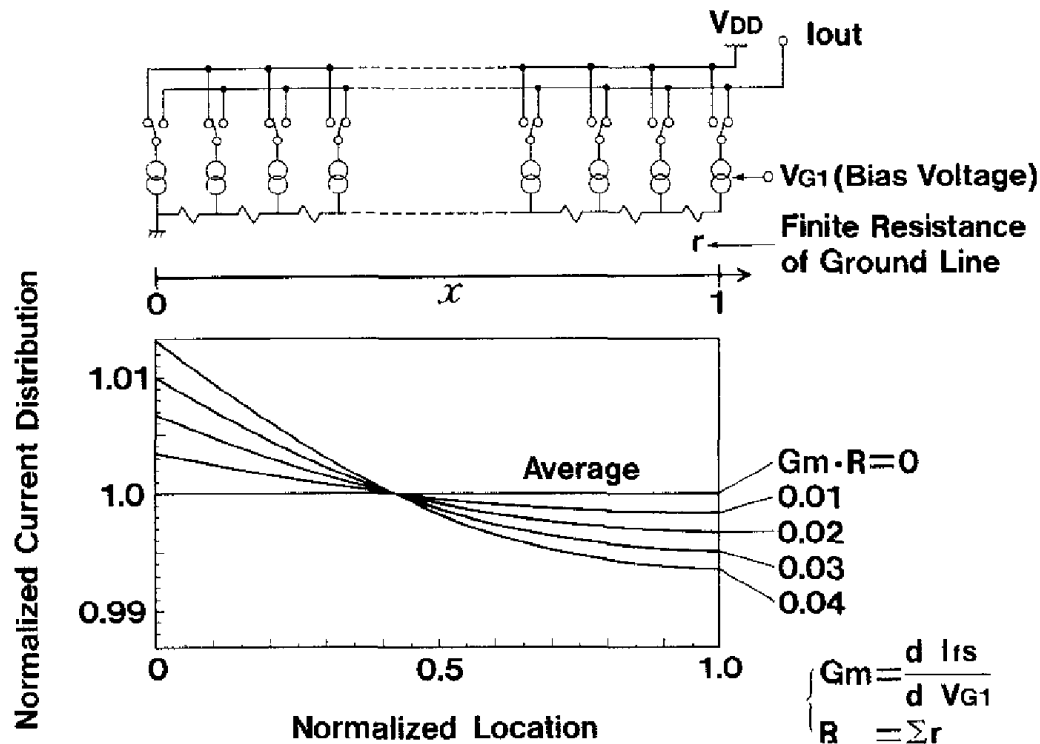


Fig. 2. Two-step decoding.

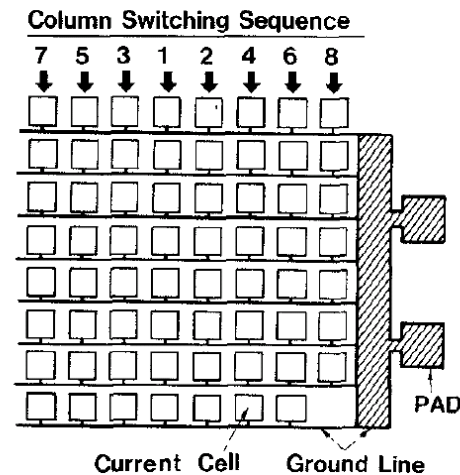
[T. Miki, Y. Nakamura, M. Nakaya, S. Asai, Y. Akasaka, and Y. Horiba, "An 80-MHz 8-bit CMOS D/A Converter," IEEE J. of Solid-State Circuits, pp. 983-988, Dec. 1986.]

# Mitigating IR Drop



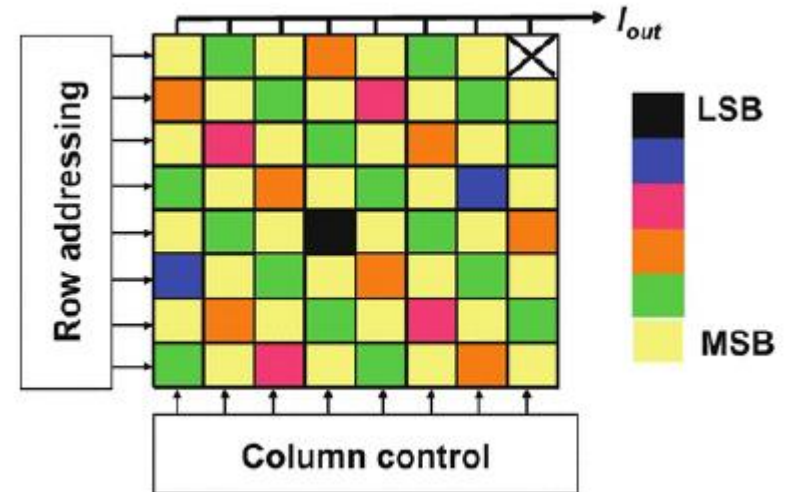
|                       |   |   |   |   |   |   |
|-----------------------|---|---|---|---|---|---|
| 1                     | 2 | 3 | 4 | 5 | 6 | 7 |
| SEQUENTIAL SWITCHING  |   |   |   |   |   |   |
| 6                     | 4 | 2 | 1 | 3 | 5 | 7 |
| SYMMETRICAL SWITCHING |   |   |   |   |   |   |

Fig. 9. Symmetrical switching.



# Common Centroid Layout Example

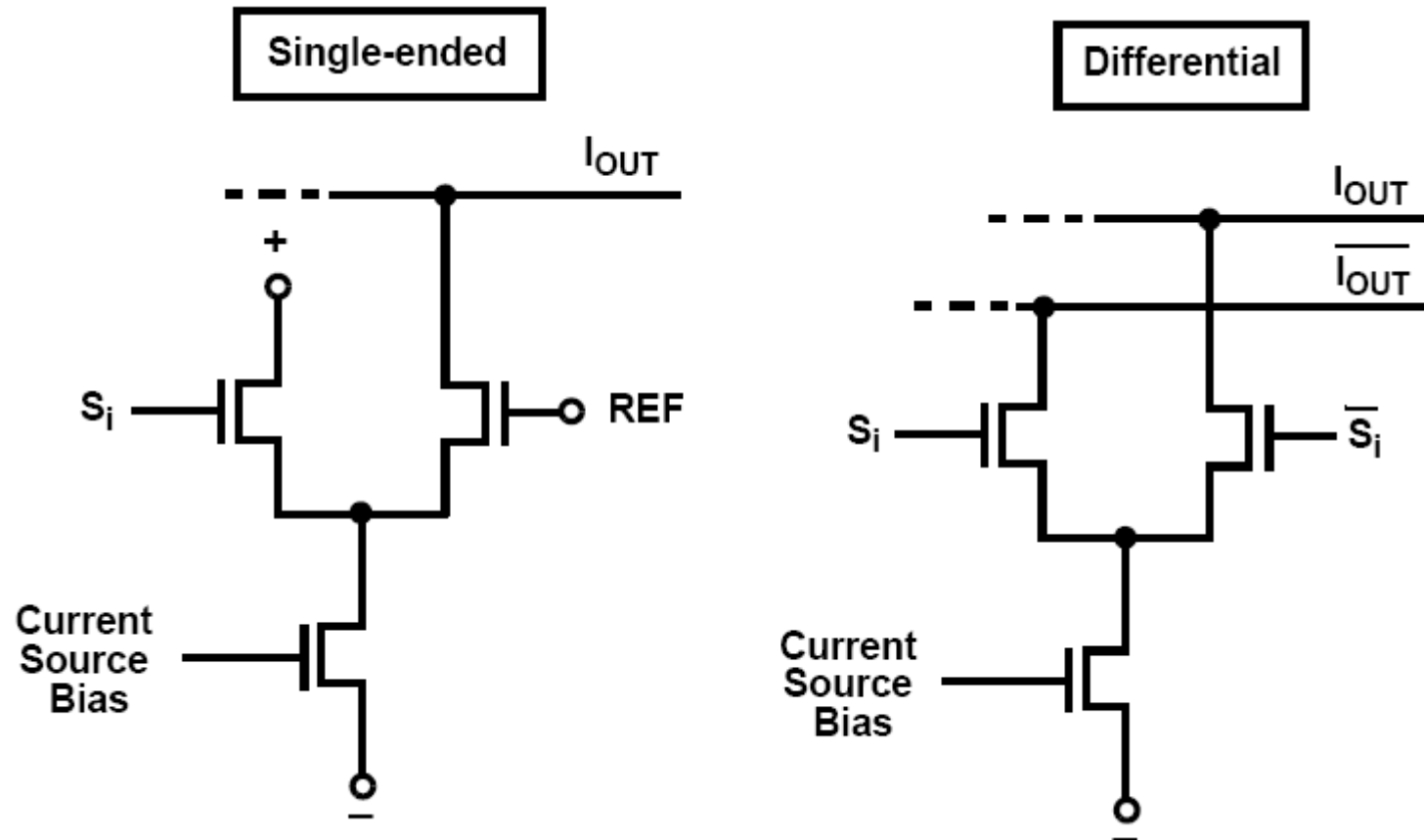
- Common centroid binary weighted array
- To cancel gradients
  - Process
  - IR drop
  - Timing



[Bastiaansen, Corne, et al. "A 10-bit 40 MHz 0.8  $\mu\text{m}$  CMOS current-output D/A converter." *Solid-State Circuits Conference, 1990. ESSCIRC'90. Sixteenth European*. Vol. 1. IEEE, 1990.]

[M. Pelgrom, *Analog-to-Digital Conversion*, 3<sup>rd</sup> Ed.]

# Basic Differential Pair Switch



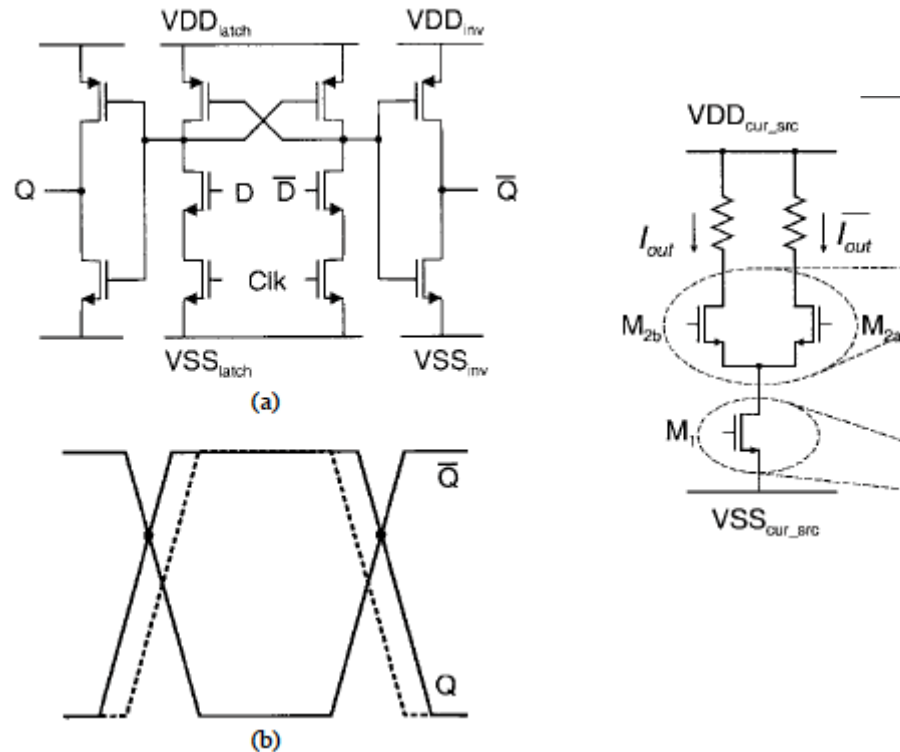
# Commonly Used Techniques

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- Retiming
  - Latches in (or close to) each current cell
  - Latch controlled by global clock to ensure that current cells switch simultaneously (independent of decoder delays)
- Make before break
  - Ensure uninterrupted current flow, so that tail current source remains active
- Low swing driver
  - Drive differential pair with low swing to minimize coupling from control signals to output
- Cascoded tail current source for high output impedance
  - Ensures that overall impedance at output nodes is code independent (necessary for good INL)

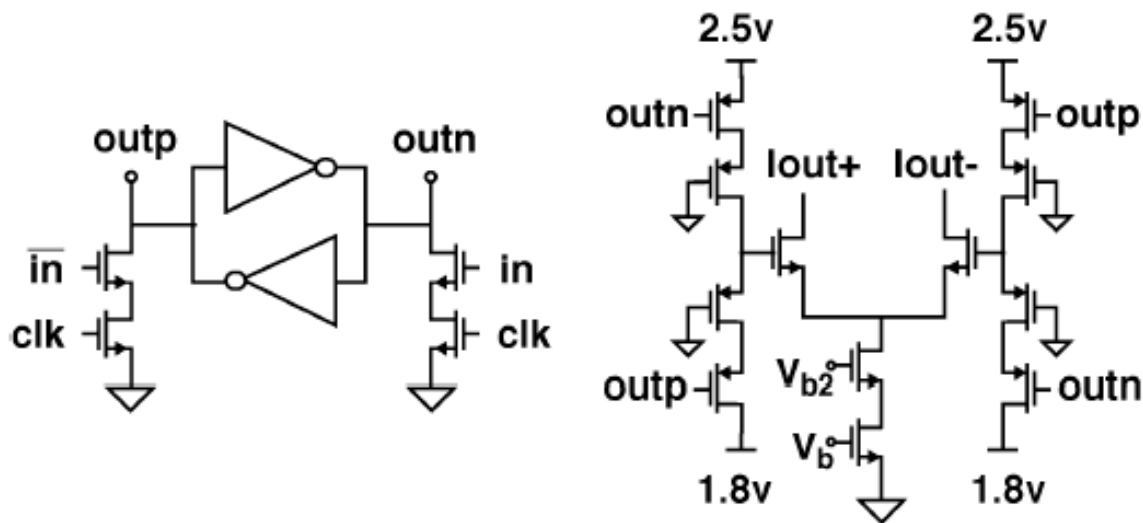


# Example Retiming Latch



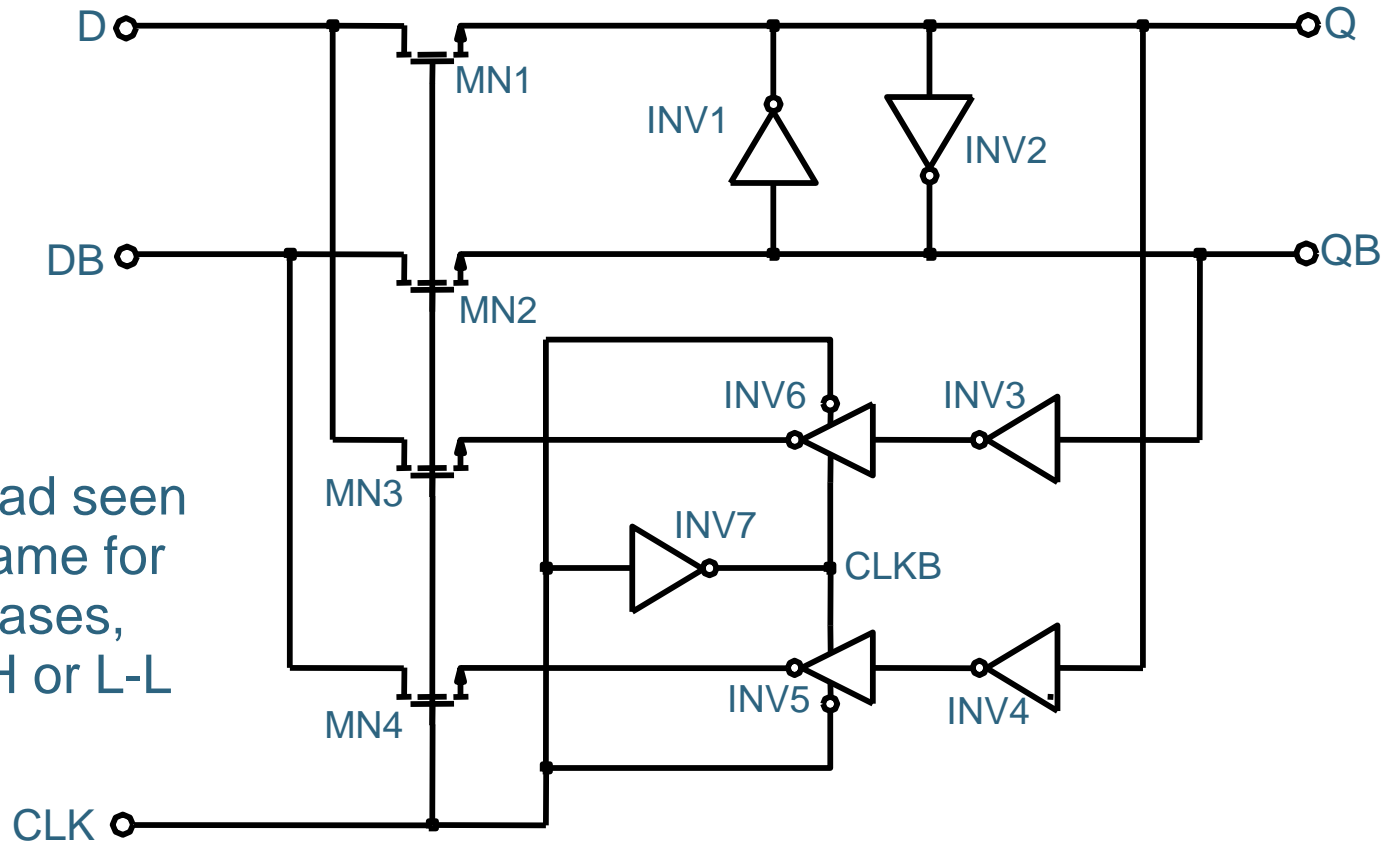
[Van der Plas, JSSC 12/99]

# Example Current Cell Implementation



[Barkin & Wooley, JSSC 4/2004]

# Constant Clock Load Latch



Capacitive load seen at CLK the same for all possible cases, H-L, L-H, H-H or L-L

Mercer, *US patent* ,7,023,255 4/4/2006